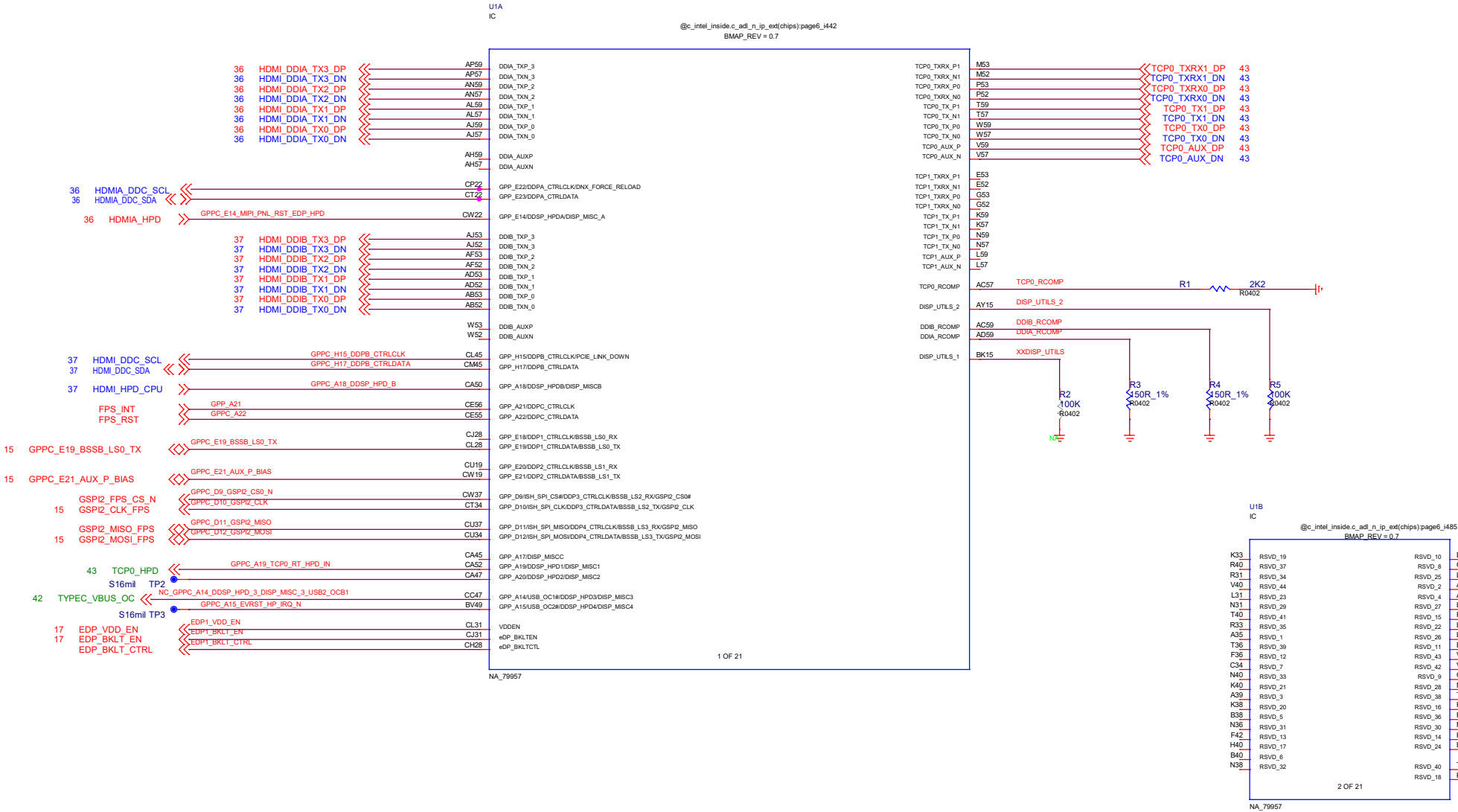
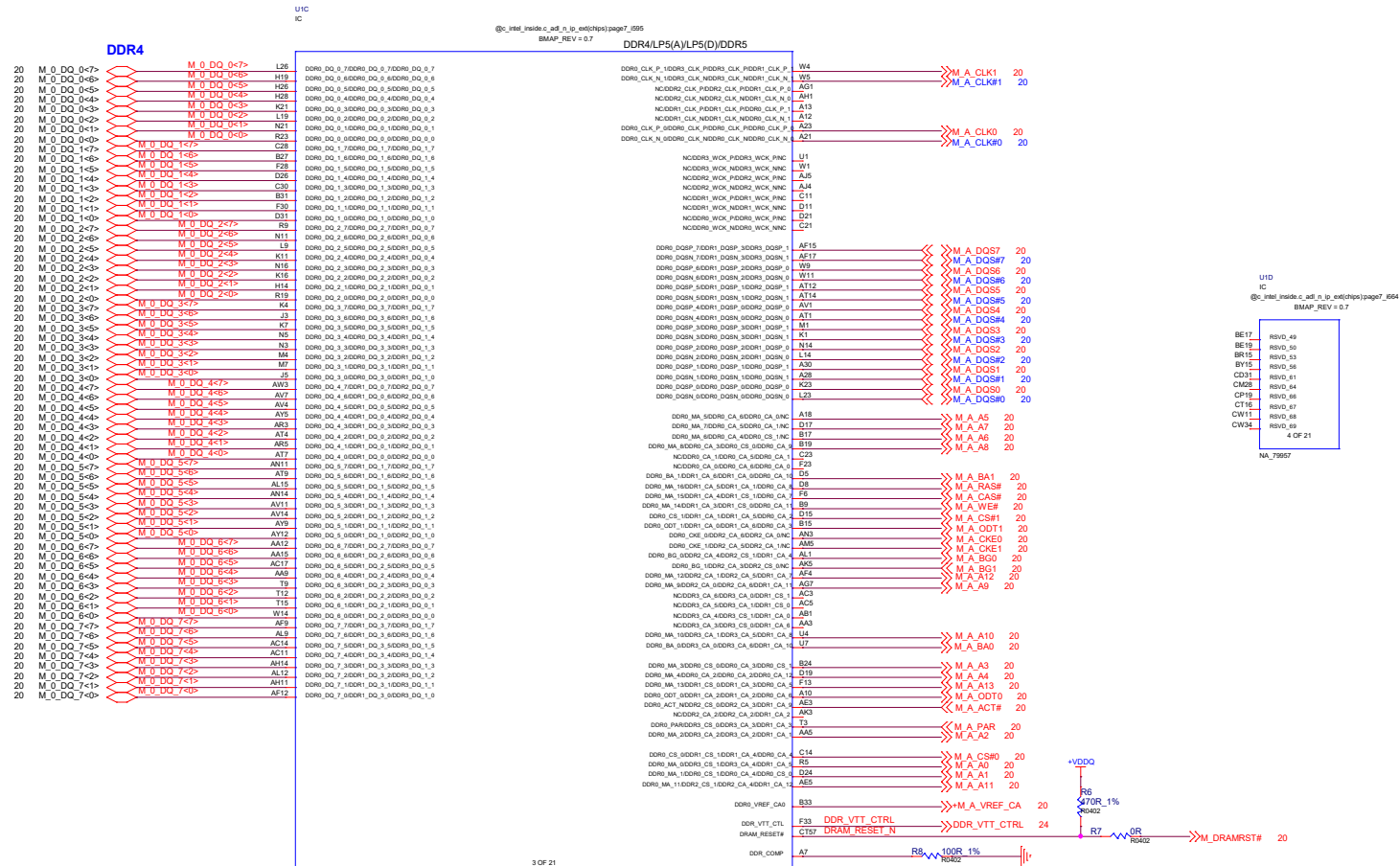


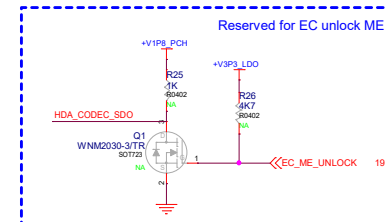
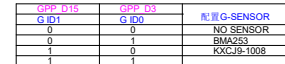
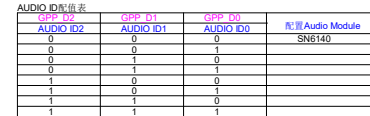
04_ADL-N MCP-DISP



05_ADL-N MCP -MEMOR



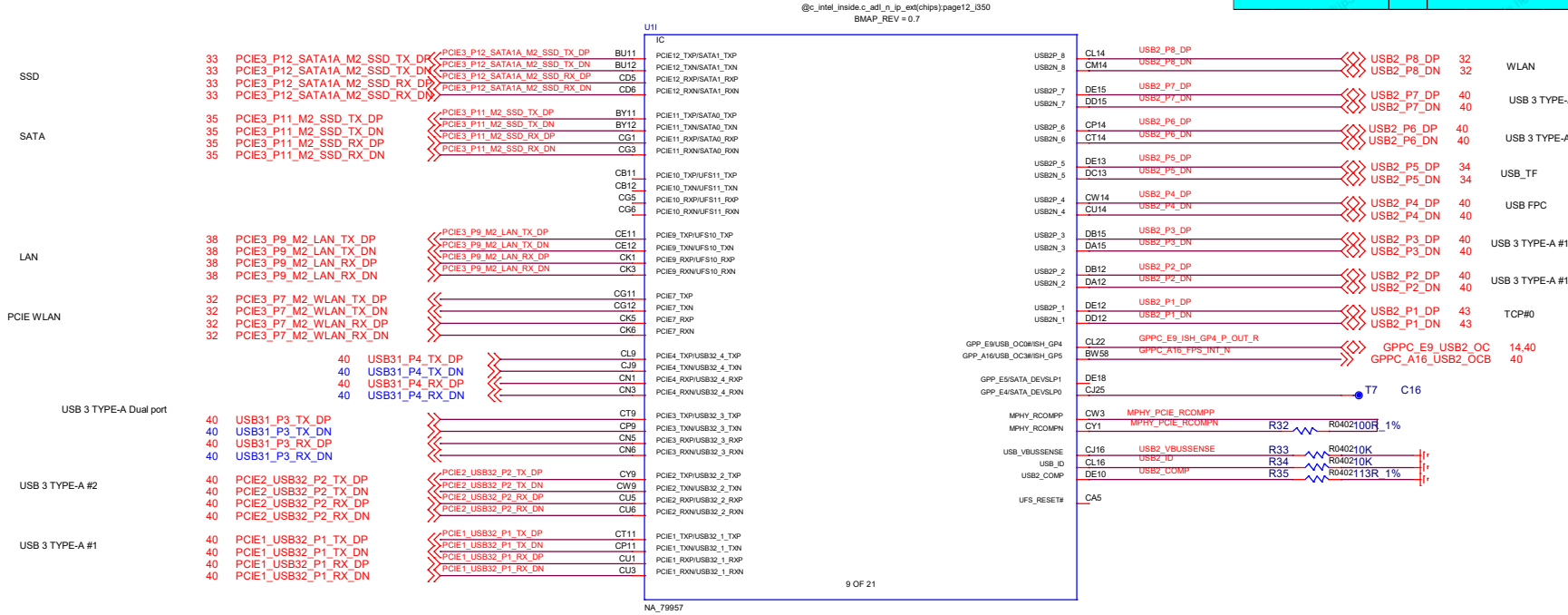
BMAP_REV = 0.7



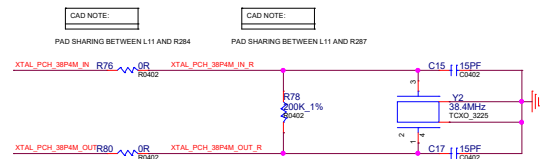
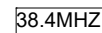
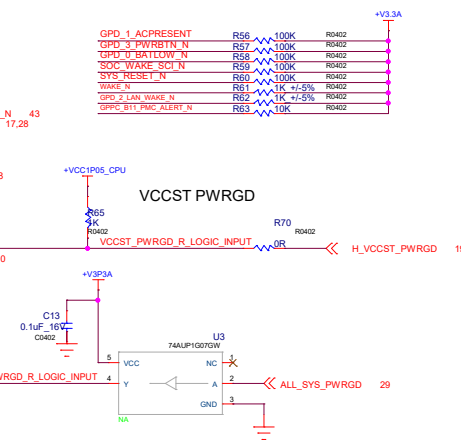
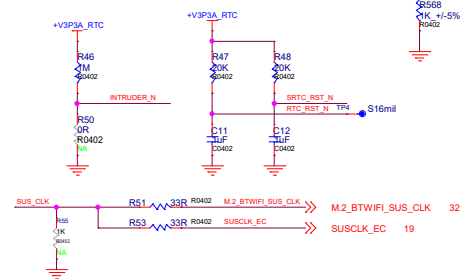
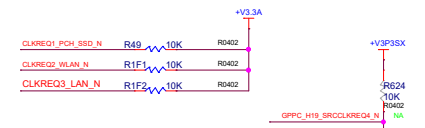
英众科技		Title _____ Drawn By _____	
Size	Document Number	Rev	
B	07_ADL-N MCP - EMMC	1.0	
Date	Monday, March 14, 2022	Sheet	7 of 45



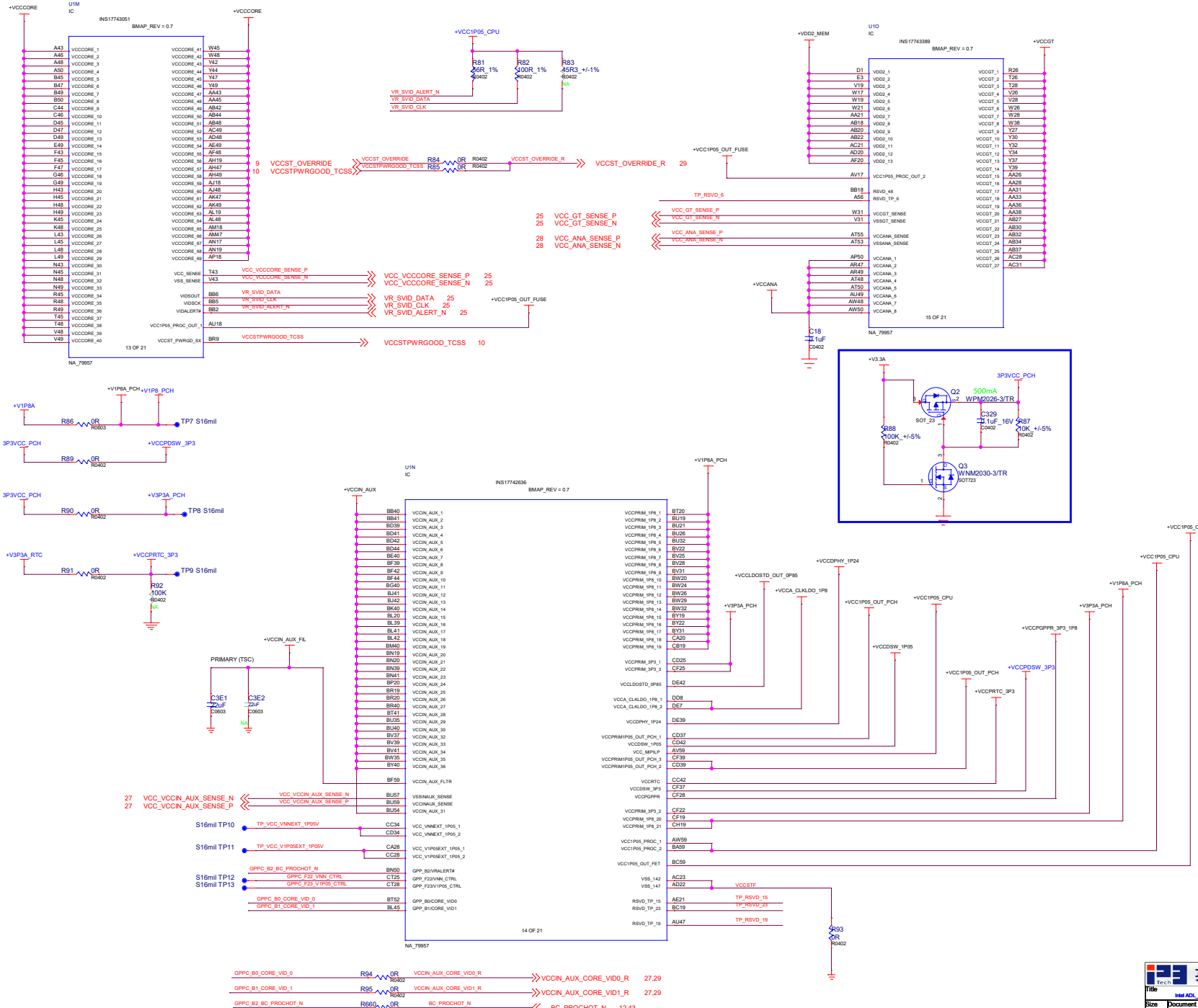
- Total 9 ModPHY Lanes
- Up to 9 PCIe* Gen3 lanes with 5 PCIe* Clks
- Up to 4 USB3.2 Gen 2x1
- Up to 2 SATA3
- 4 USB3.2 Gen 1x1 + PCIe* muxed lanes
 - 1 PCIe* only lanes
 - 2 PCIe + UFS2.1 muxed lane
 - 2 PCIe + SATA muxed lane



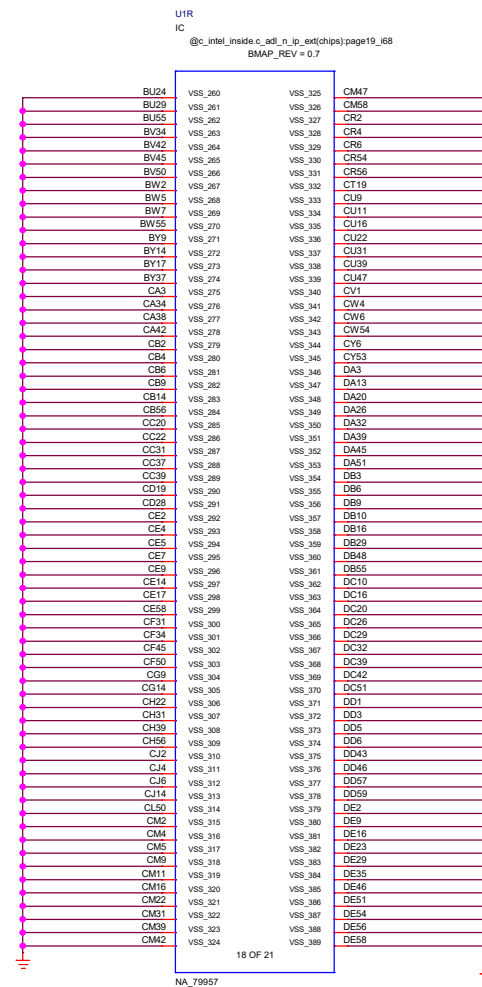
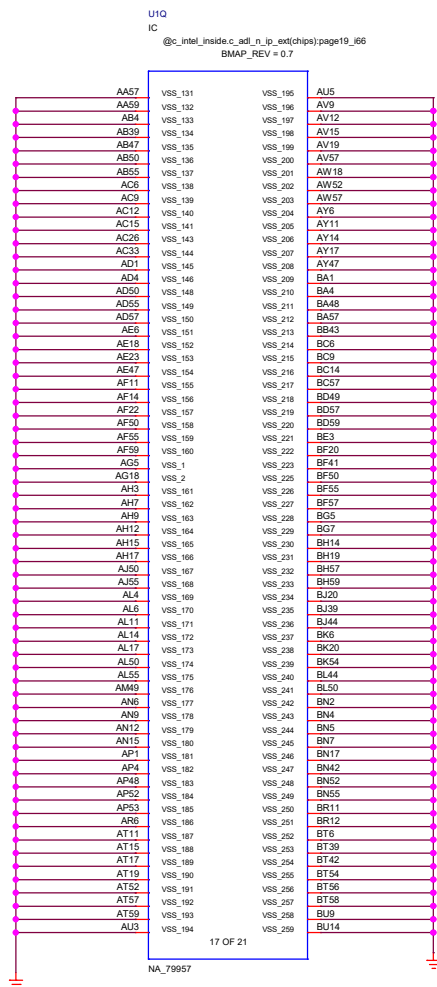
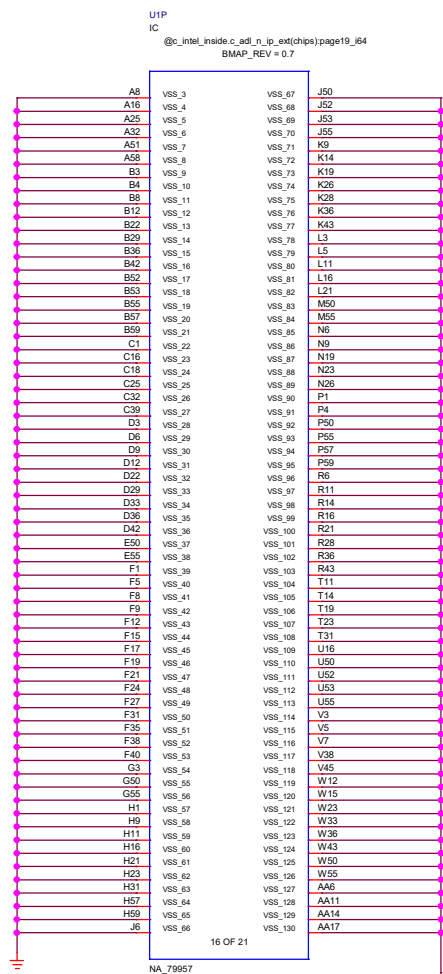
32.768KHZ



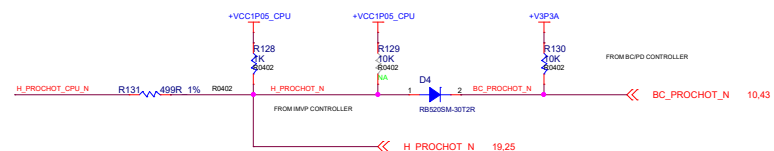
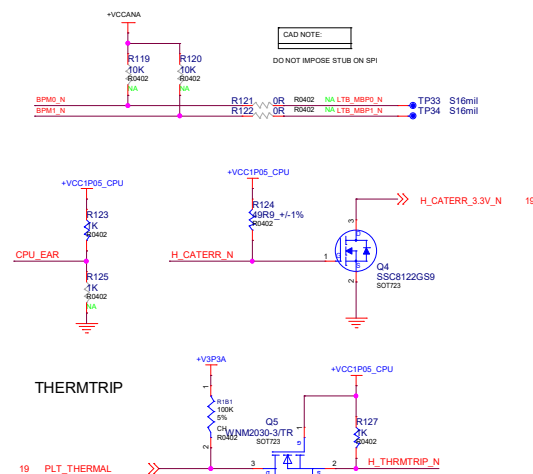
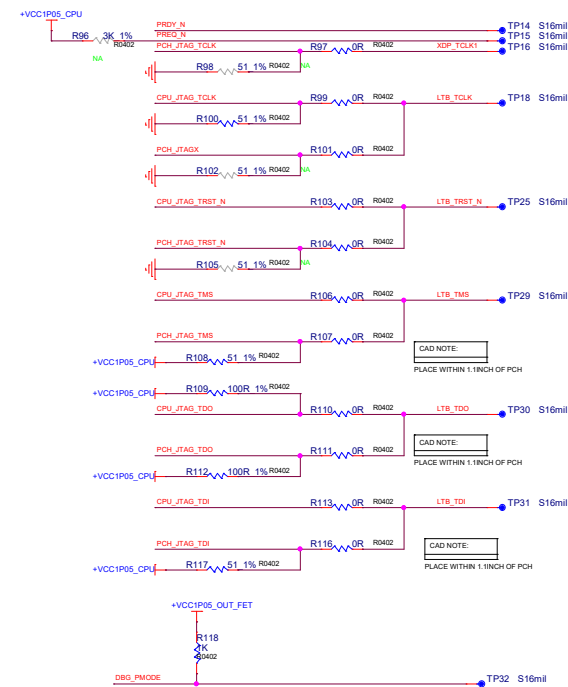
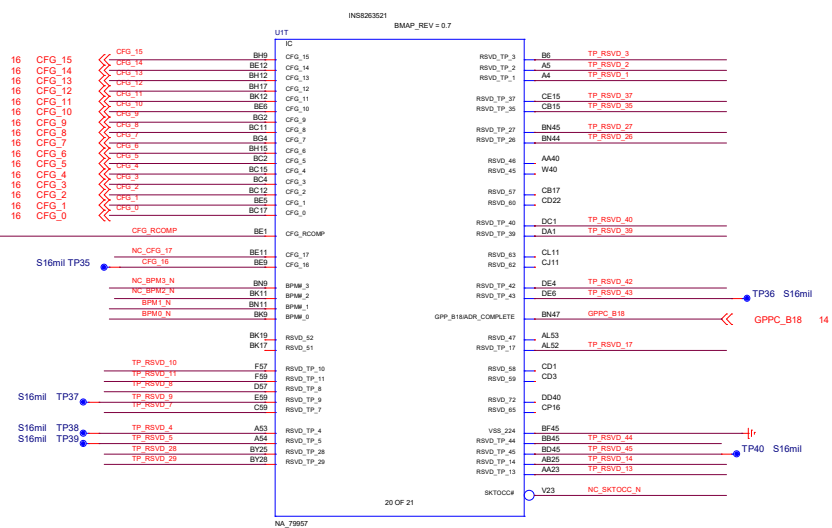
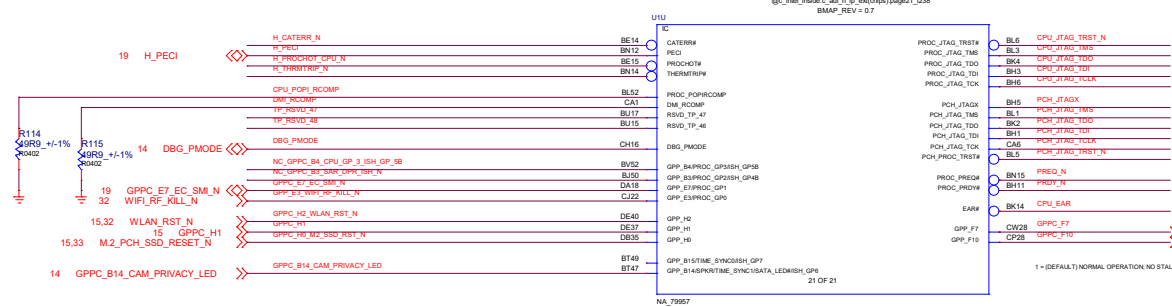
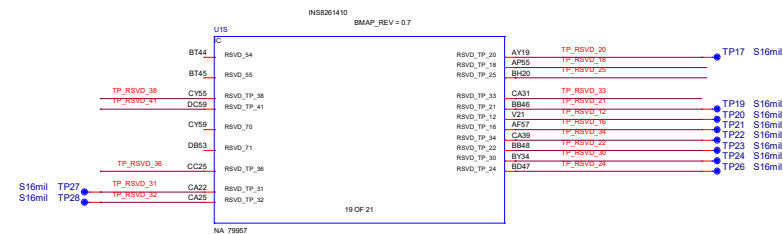
10 ADL-N MCP - CPU-POWER



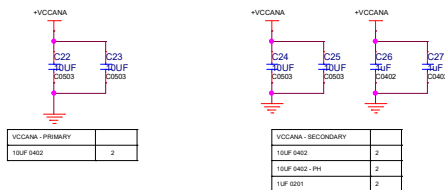
11_ADL-N MCP GND



12 ADL-N MCP FIV& CPU&DEB

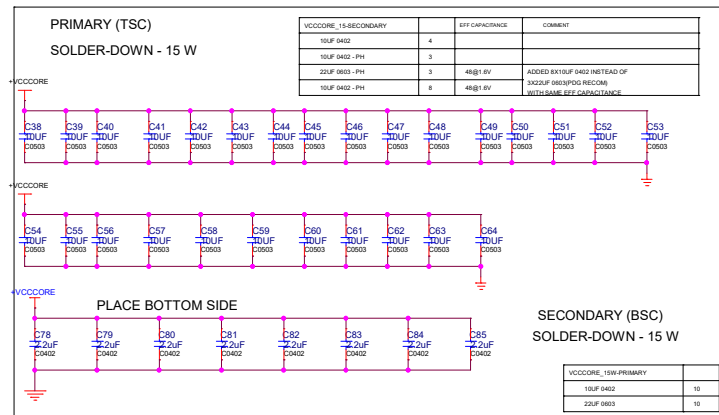


VCCANA PDBOM

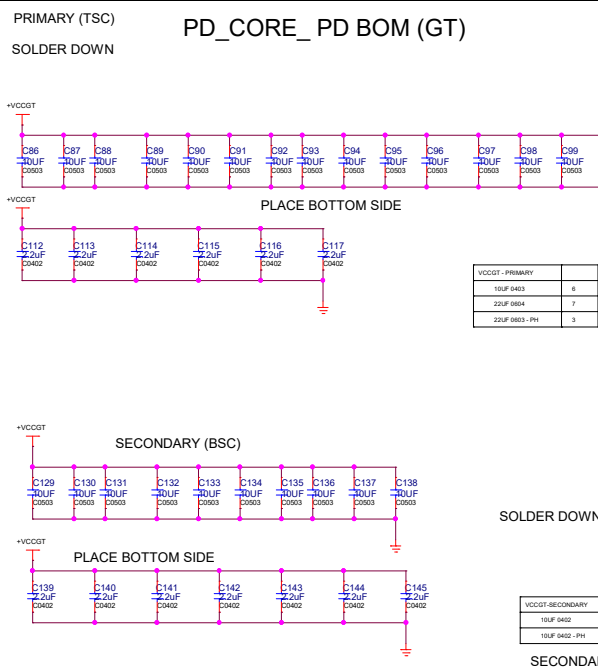


PLACE BOTTOM SIDE

PD_CORE_PD BOM (VCCCORE)

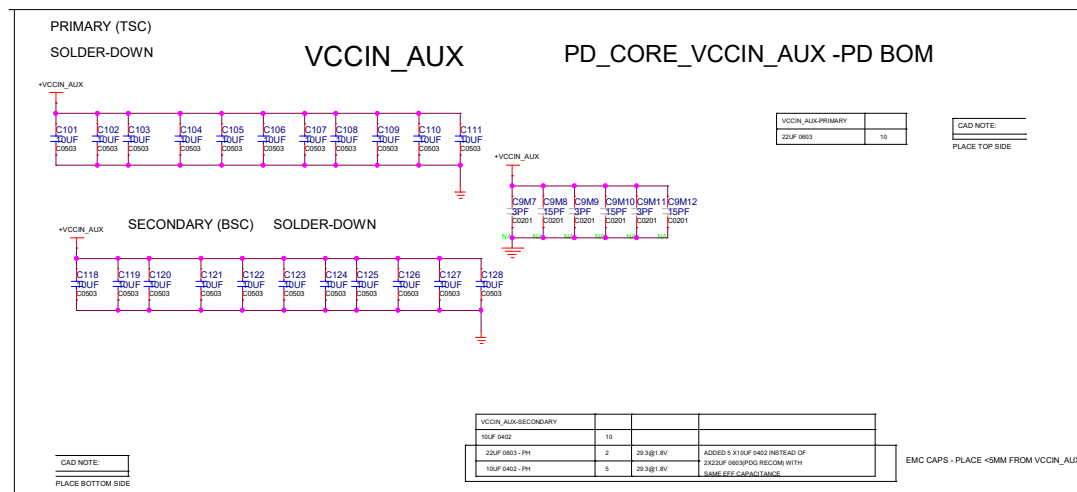
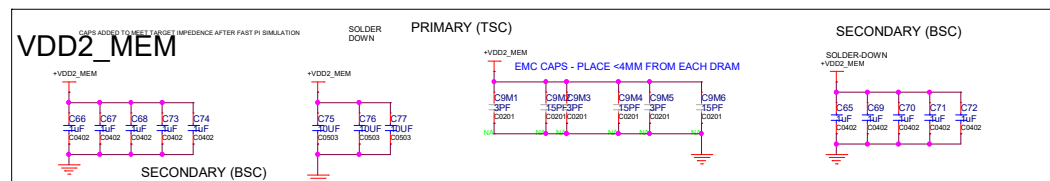
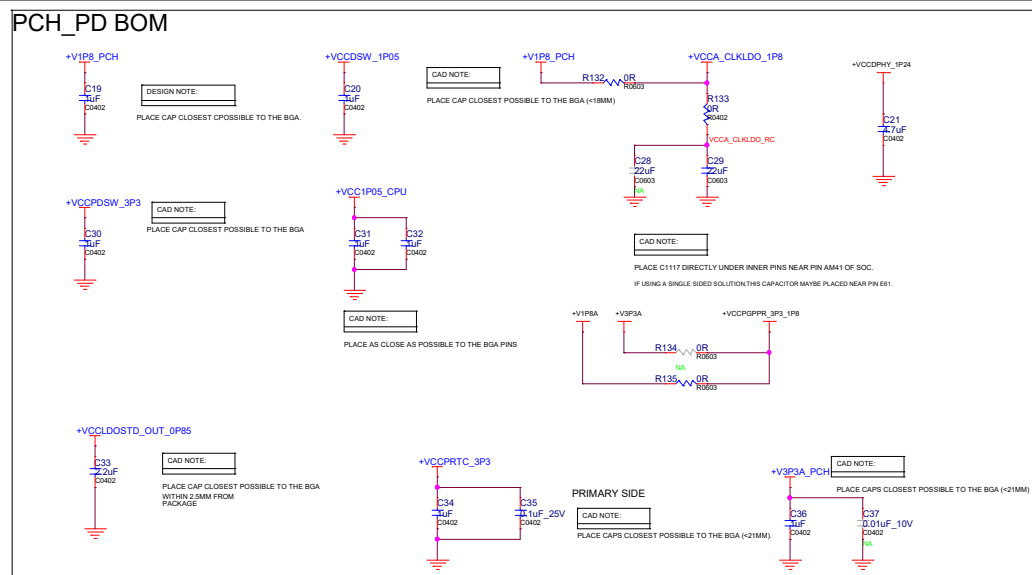


PD_CORE_PD BOM (GT)



SOLDER DOWN

SECONDARY SIDE

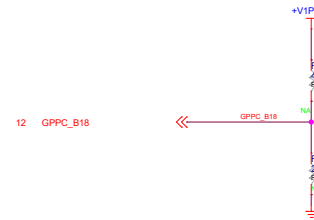


14_PCH STRAPS



TOP SWAP OVERRIDE

HIGH- TOP SWAP ENABLED
LOW-DISABLED
WEAK INTERNAL PD 20K
SAMPLING- PCH_PWROK



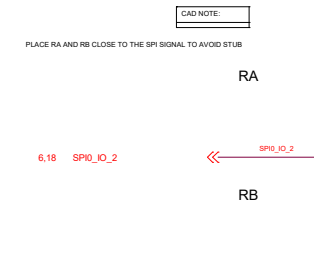
NO REBOOT

HIGH - NO REBOOT
LOW - REBOOT ENABLED
WEAK INTERNAL PD 20K
SAMPLING- PCH_PWROK



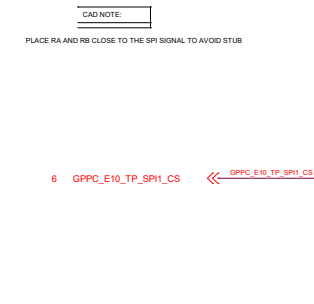
TLS CONFIDENTIALITY

LOW - TLS CONFIDENTIALITY DISABLE
HIGH - TLS CONFIDENTIALITY ENABLE
WEAK INTERNAL PD 20K
SAMPLING - RSMRSTB

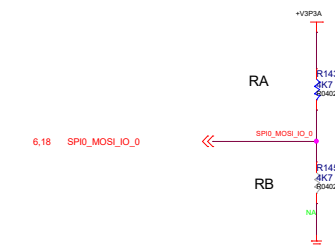


CONSENT STRAP

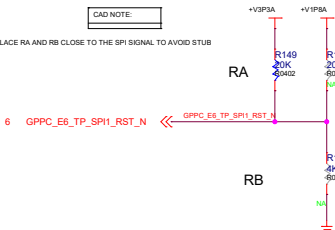
HIGH: DISABLED
LOW: ENABLED
NO INTERNAL PU/PD
SAMPLING - RSMRSTB



ESPI OR EC LESS
HIGH: ESPI IS DISABLED
LOW: ESPI SELECTED
WEAK INTERNAL PD 20K
SAMPLING - RSMRSTB



BOOT HALT
HIGH - DISABLED
LOW - ENABLED
NO INTERNAL PU/PD
SAMPLING - RSMRSTB



JTAG ODT DISABLE
LOW: JTAG ODT DISABLED
HIGH: JTAG ODT ENABLED
NO INTERNAL PU/PD
SAMPLING - RSMRSTB

CAD NOTE:
PLACE RA AND RB CLOSE TO THE SPI SIGNAL TO AVOID STUB



RA

RB

DESIGN NOTE:
NOTE 2: STUFF RA WHEN WE ARE VALIDATING 100MHZ FLASH

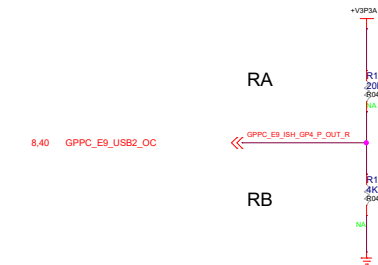
A0 PERSONALITY STRAP

HIGH: DISABLED
LOW: ENABLED
NO INTERNAL PU/PD
SAMPLING - RSMRSTB



DFXTESTMODE

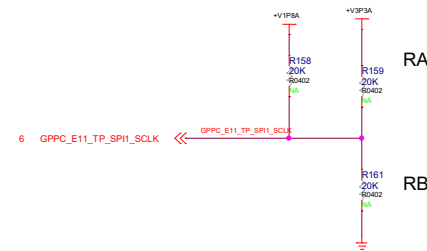
PGDMON
HIGH - DFXTESTMODE DISABLED(DEFAULT)
LOW - DFXTESTMODE ENABLED
WEAK INTERNAL PU 20K
SAMPLING - RSMRSTB



RA

RB

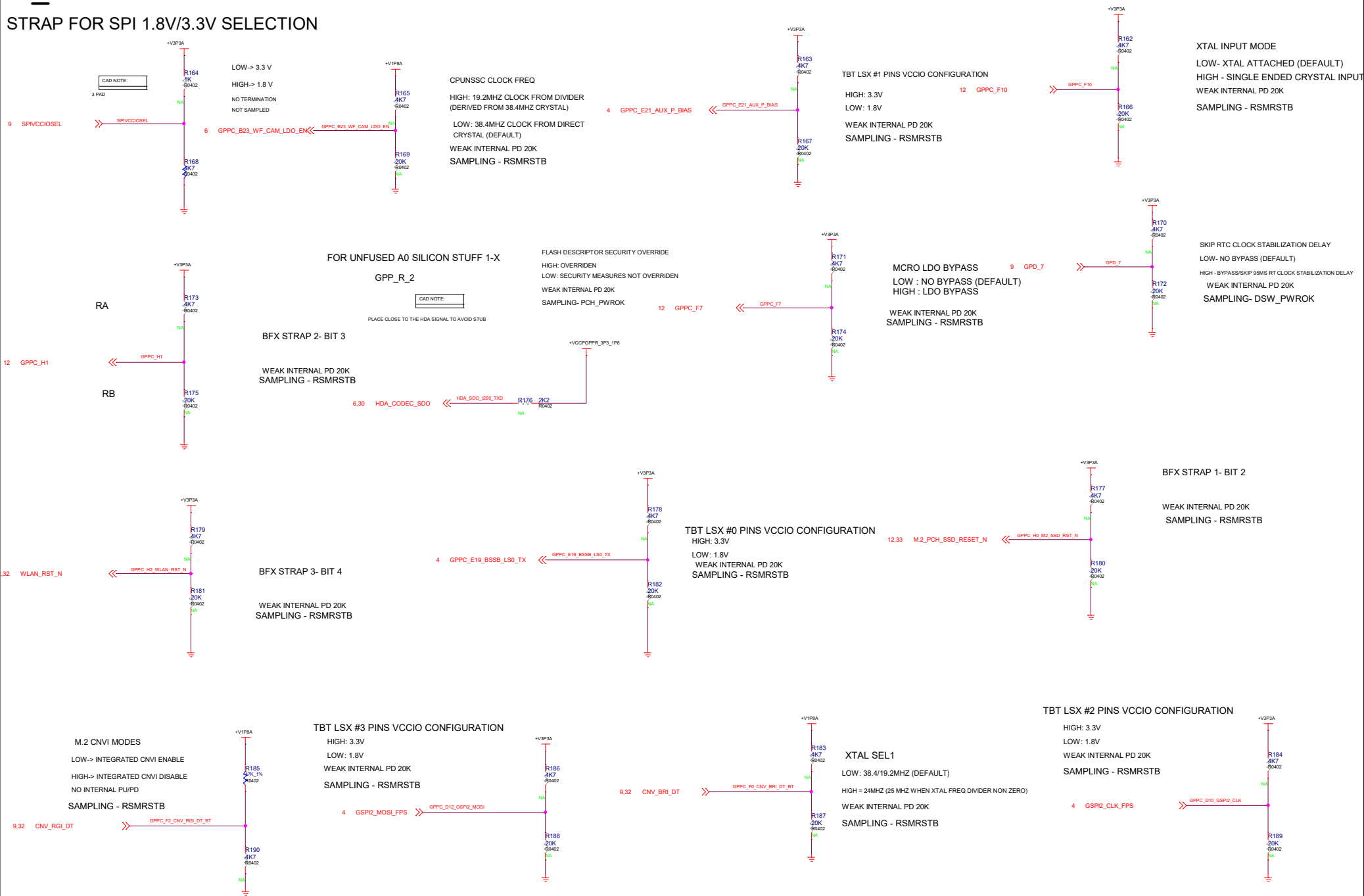
CAD NOTE:
PLACE RA AND RB CLOSE TO THE SPI SIGNAL TO AVOID STUB



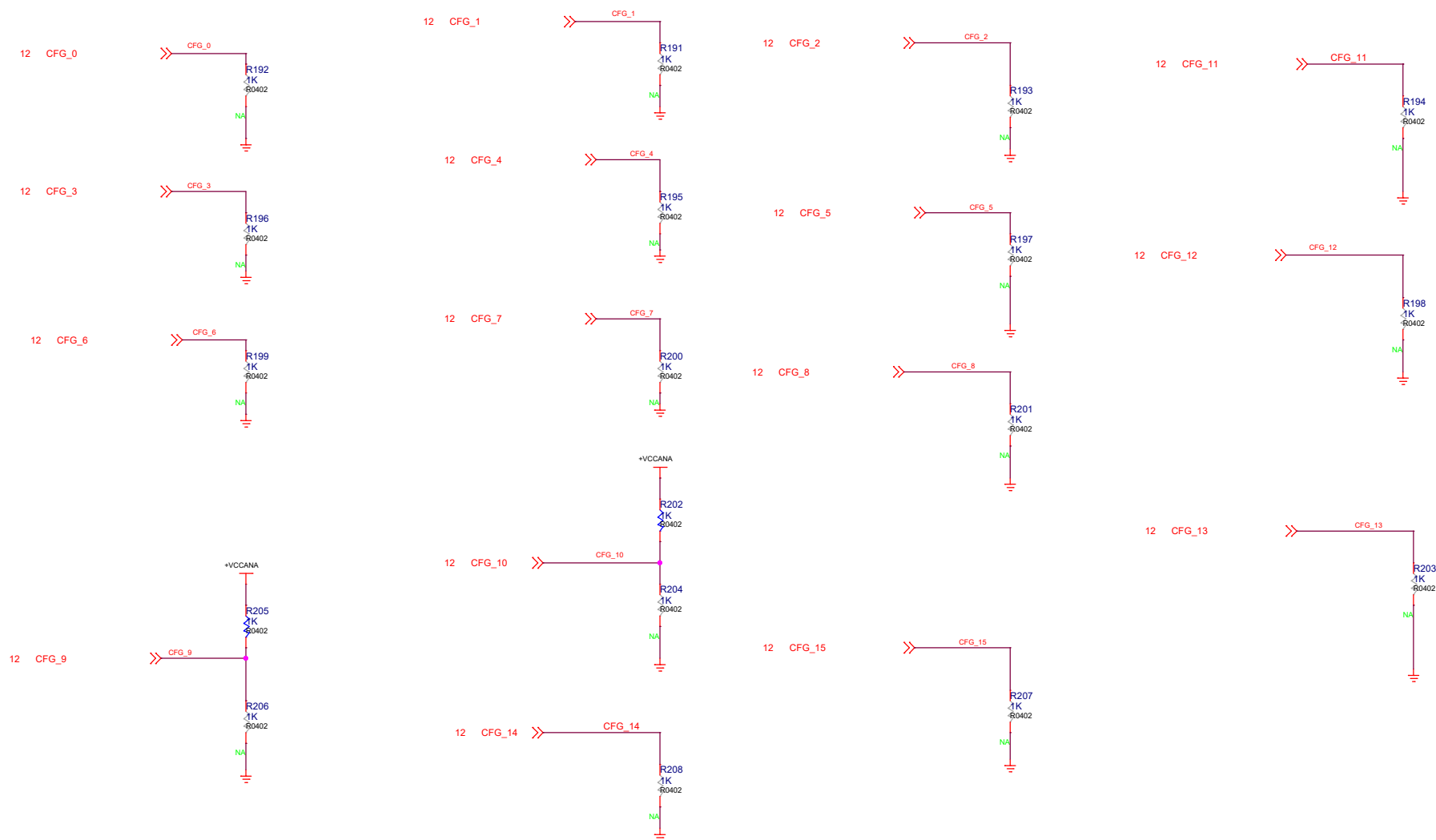
RA

RB

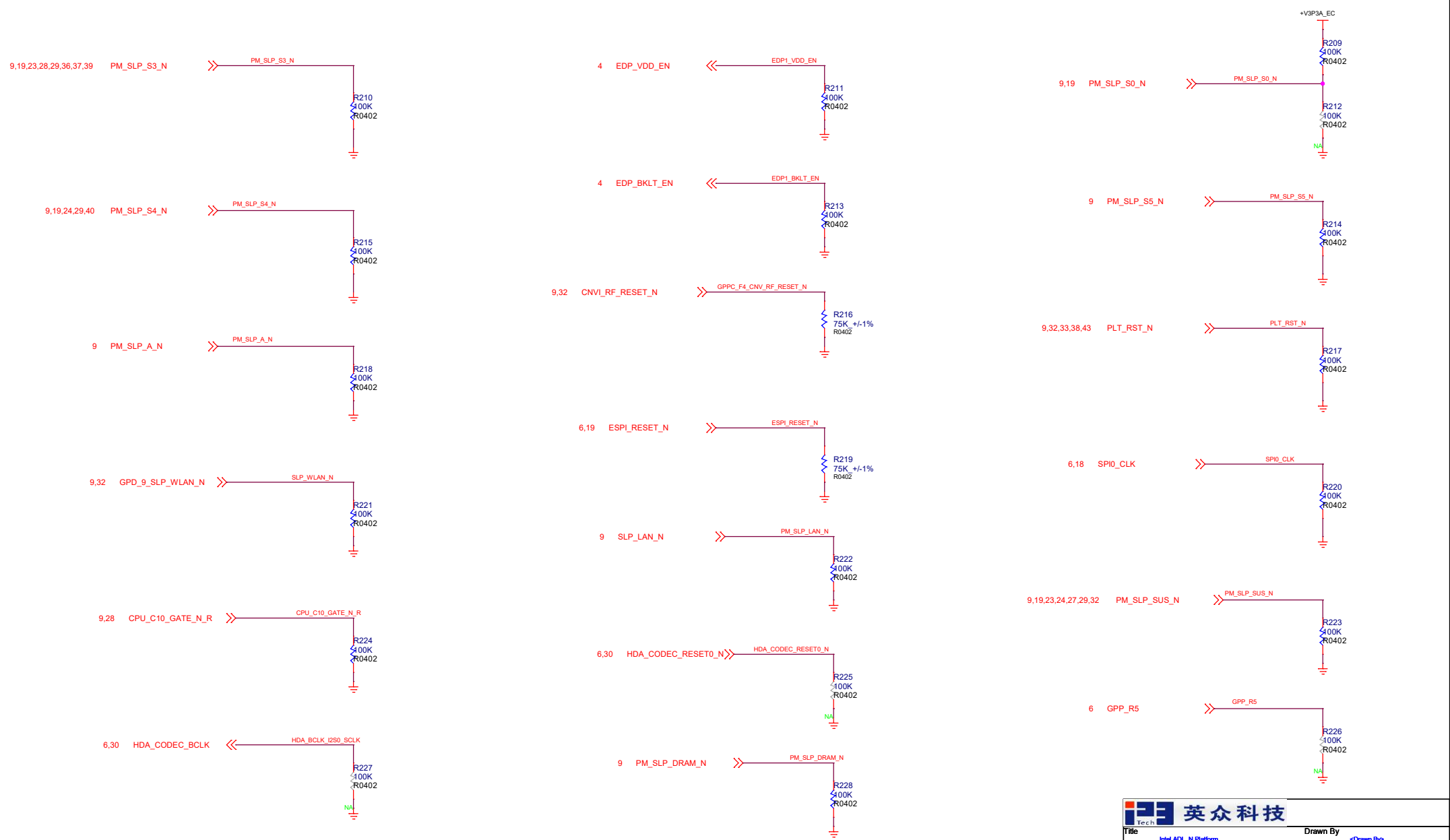
STRAP FOR SPI 1.8V/3.3V SELECTION



16 CPU STRAPS

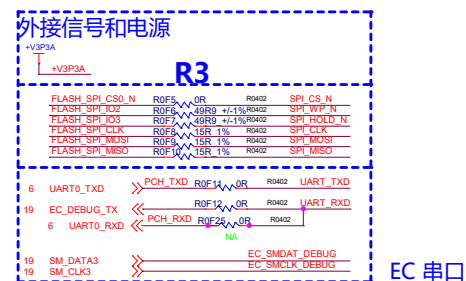
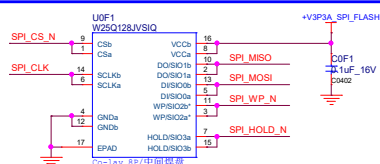
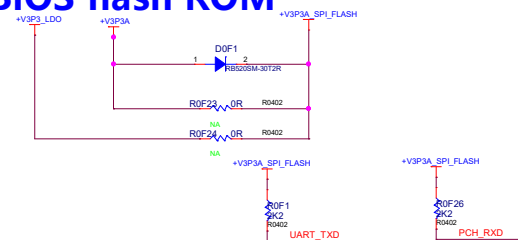


17_GLITCH FREE CIRCUIT

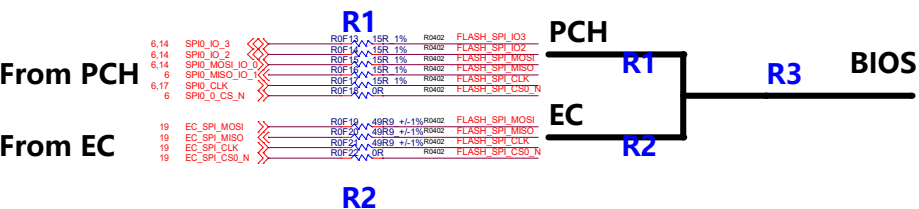
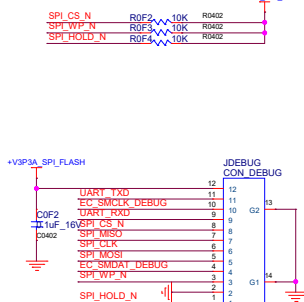


18_SYSTEM FLASH

BIOS flash ROM



EC 串口



TPM2.0(INFINEON)

6.18.1.1.7 1-Load Branch Topology (Device Down) with EC Wired-OR Flash Sharing

Figure 242. SPI0 1-Load Branch Topology (Device Down) with EC Wired-OR Flash Sharing Diagram

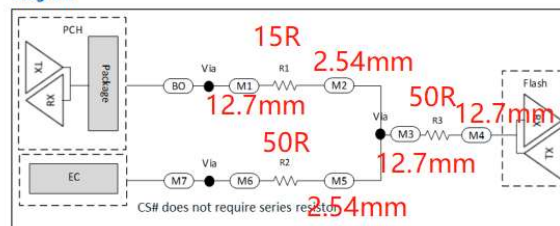
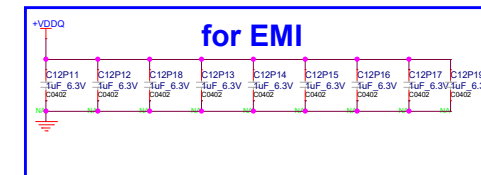
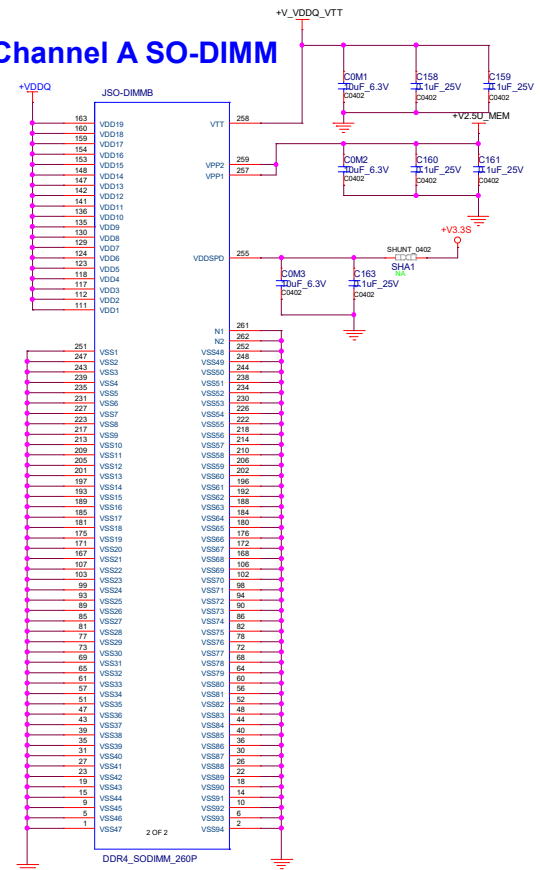
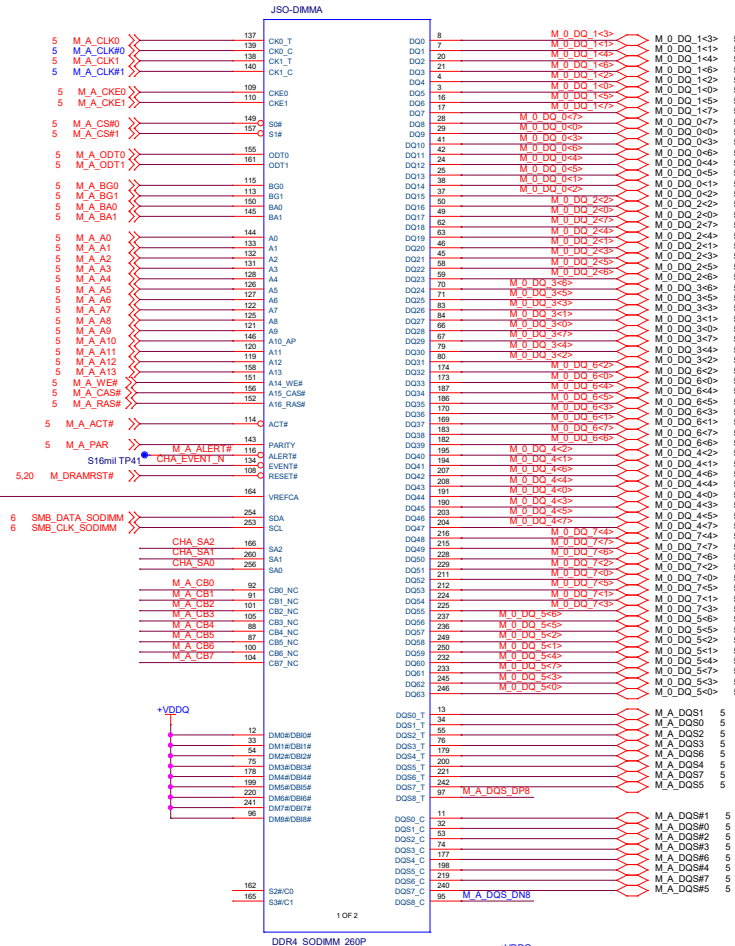
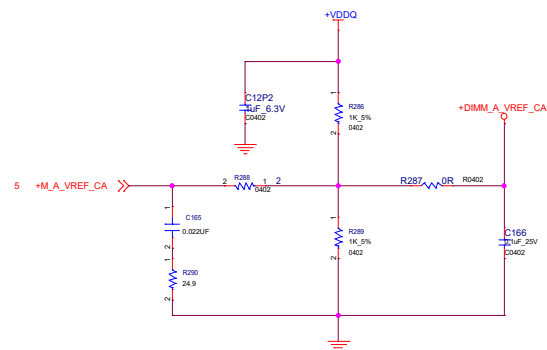
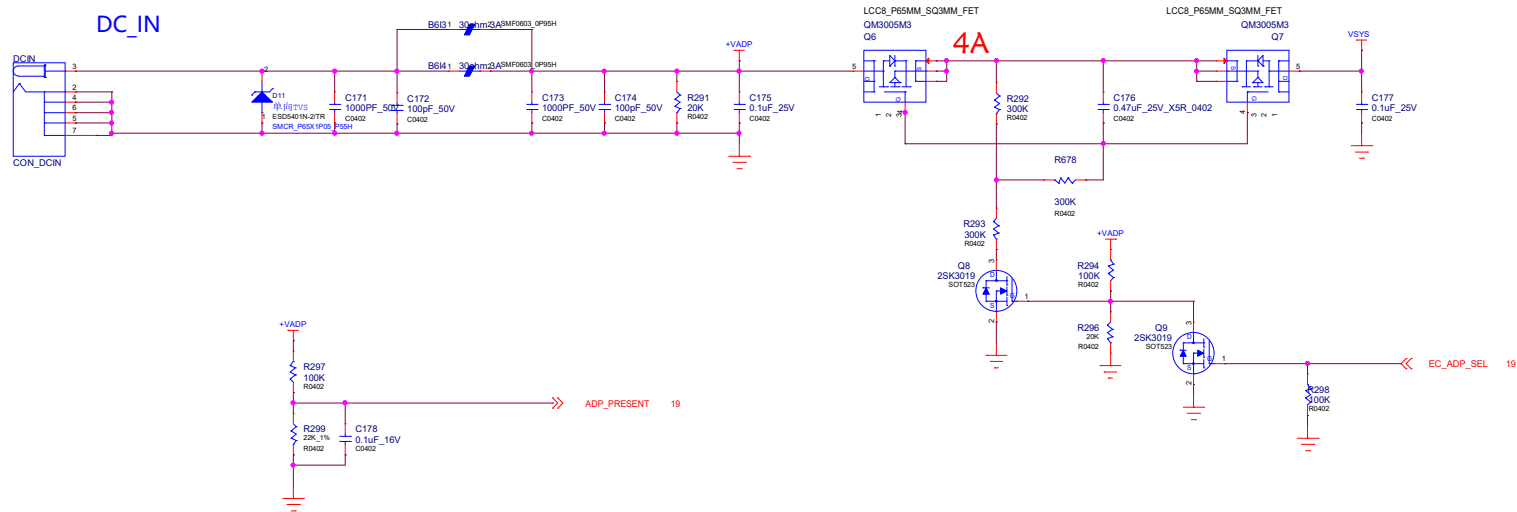


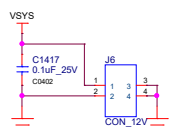
Table 443. 1-Load Branch Topology (Device Down) with EC Wired-OR Flash Sharing Notes

Note	Detail
Number of vias allowed	5
Reference plane	Continuous ground only
Max frequency	50 MHz
EC and PCH branch requirement	Delta between M1 + M2 and M5 + M6 shall not exceed 25.4 mm
R1	0 Ω placeholder for 1.8V and 15Ω for 3.3V. To be placed on SPI0_CLK, SPI0_MISO, SPI0_MOSI, SPI0_IO2 and SPI0_IO3.
R2	50 Ω for 1.8V and 50 Ω for 3.3V. To be placed on SPI0_CLK, SPI0_MISO, SPI0_MOSI, SPI0_IO2 and SPI0_IO3.
R3	33 Ω for 1.8V and 50 Ω for 3.3V. To be placed on SPI0_CLK, SPI0_MISO, SPI0_MOSI, SPI0_IO2 and SPI0_IO3.
Minimum length	[1] M1, M3, M4 and M6: 12.7 mm [2] M2 and M5: 2.54 mm
Device AC timing characteristics	Data input setup time < 2 ns for 1.8V and 3.3V Data input hold time < 3 ns for 1.8V and 3.3V 1.5 ns < CLK to DATA output valid time < 7.5 ns for 1.8V 1.5 ns < CLK to DATA output valid time < 7 ns for 3.3V
Length matching between CLK and DATA/ CS# signals	12.7 mm
Trace spacing between DATA and DATA signals	0.250 mm
Trace spacing between CLK and DATA/ other signals	0.375 mm
Signal name/ list	SPI0_CLK, SPI0_MOSI, SPI0_MISO, SPI0_IO2, SPI0_IO3, SPI0_CS[0:2]#

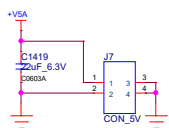




预留外部供电19v

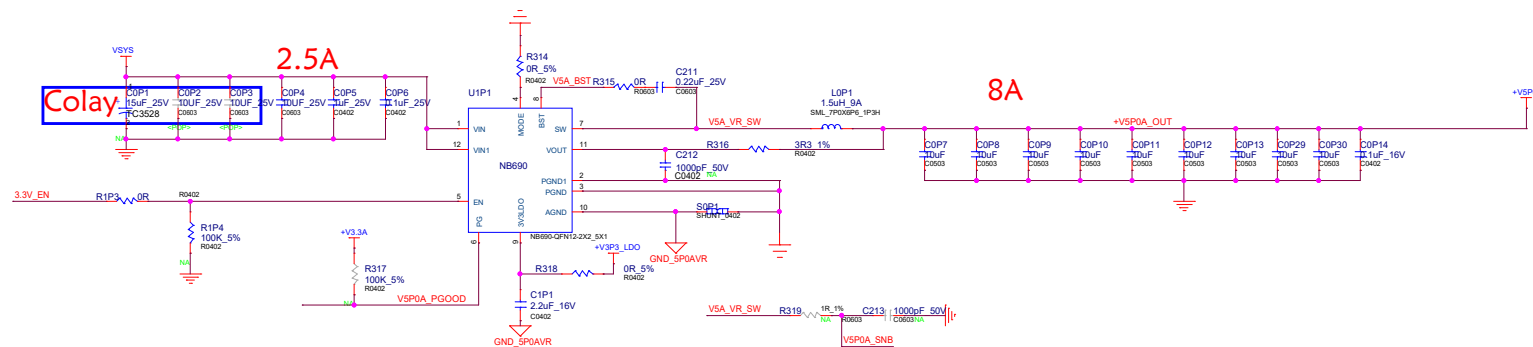


预留5v

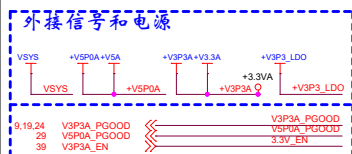
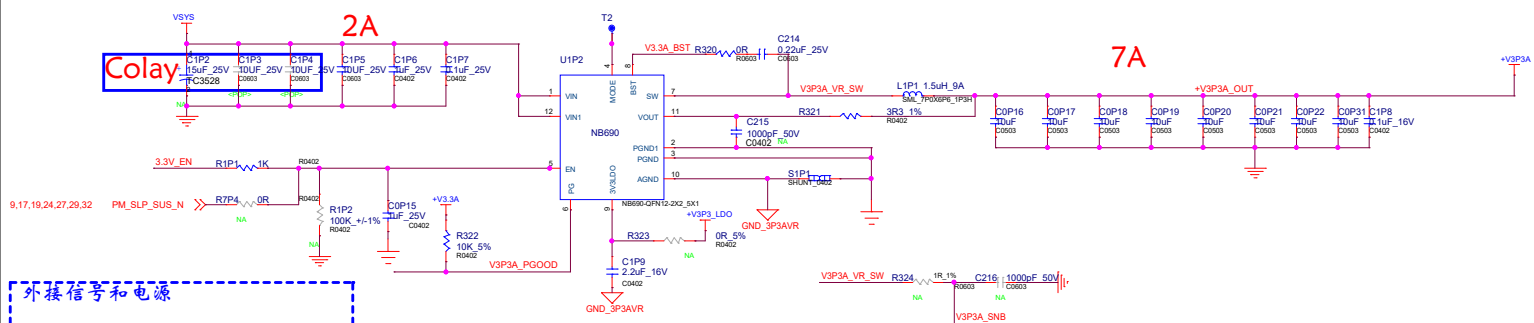


23_PWR_+5V/+3V/SX/RTC

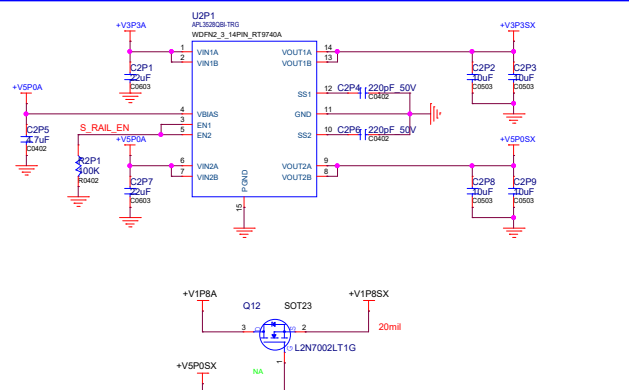
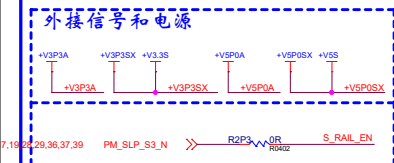
+V5P0A



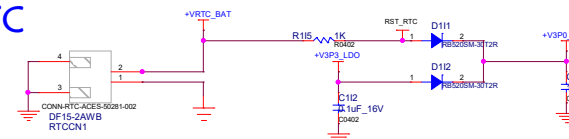
+V3P3A



S电



RTC

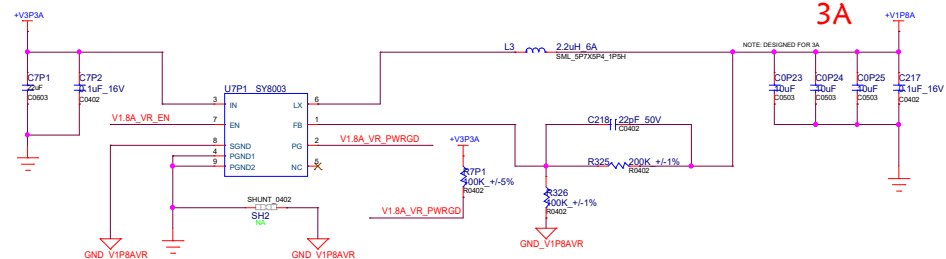
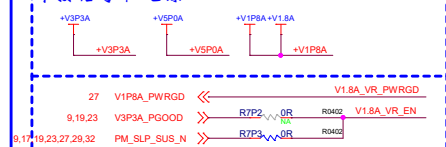


外接信号和电源



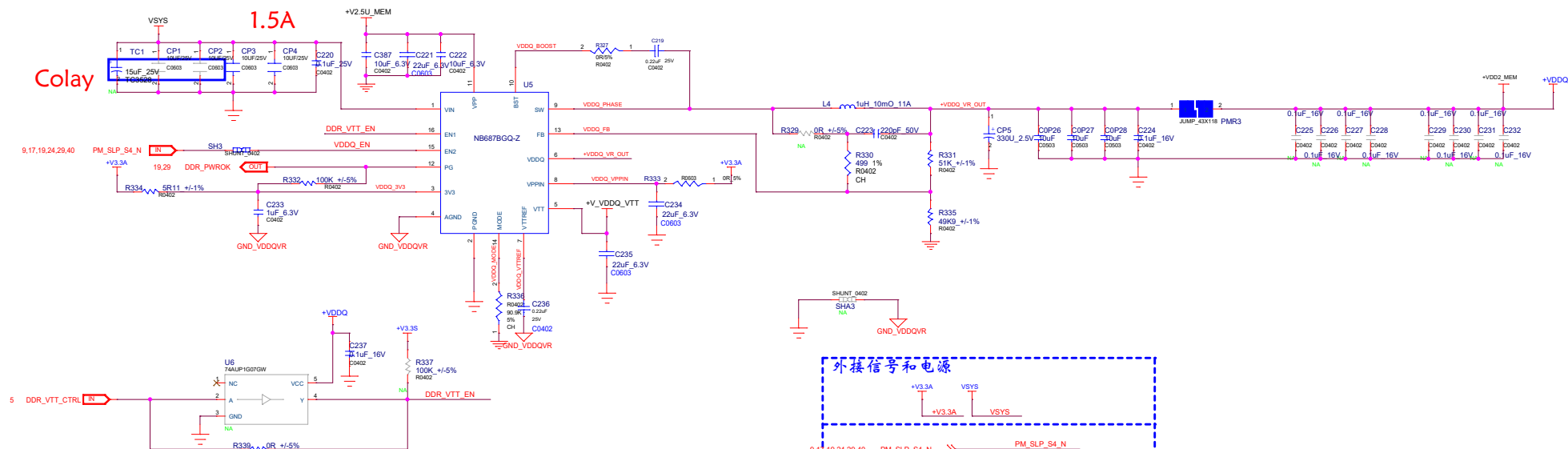
+V1P8A

外接信号和电源

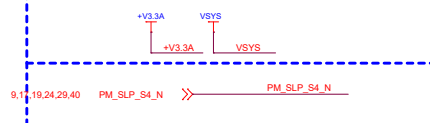


Colay

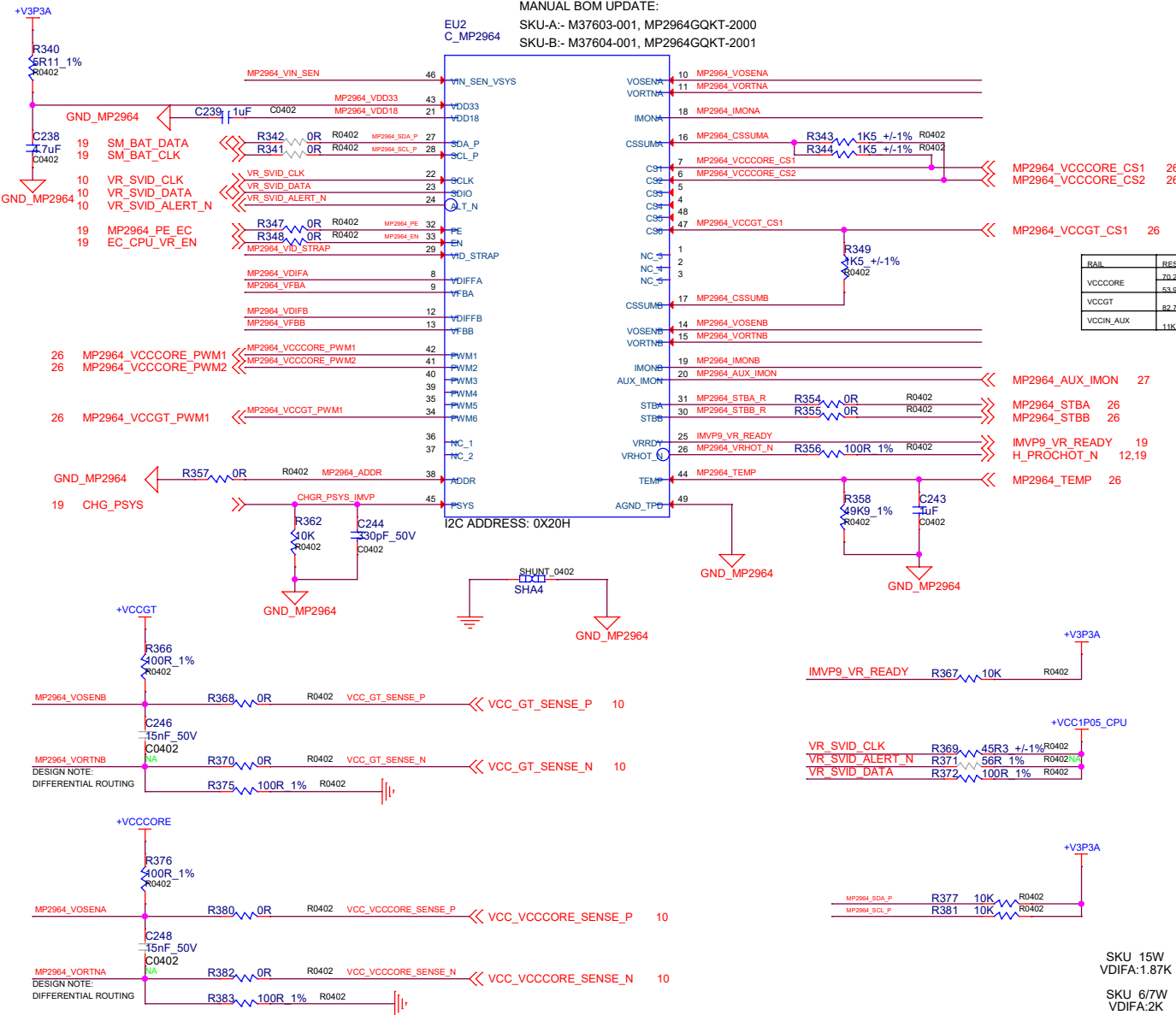
1.5A



外接信号和电源



25_PWR_IMVP CONTROLLER

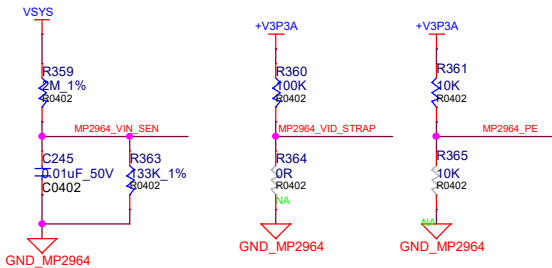
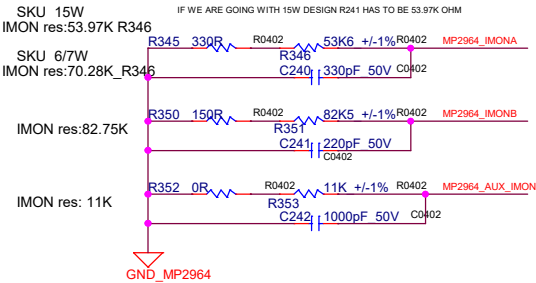


VCCIA	(VCCCORE)
VOUT	= SVID
IMAX	= 53 A
FSW	= 800KHZ

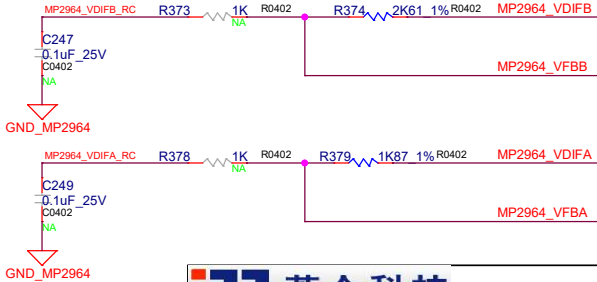
VCCGT	
VOUT	= SVID
IMAX	= 29A
FSW	= 800KHZ

VID_STRAP LEVEL	HIGH	LOW
VID STEP	0.005V	0.010V

RAIL	RES	CAP	ICCMAX
VCCORE	70.28K	330PF	37A
VCCGT	53.97K	330PF	53A
VCCIN_AUX	82.75K	220PF	29A
	11K	220PF	27A

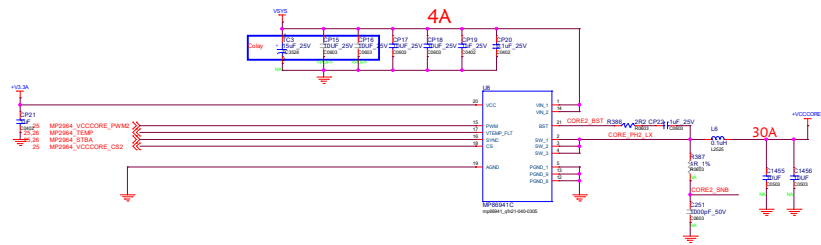
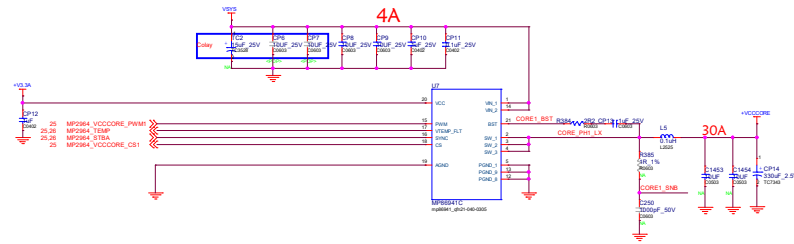


CAD NOTE:
PLACE R121,R123,R126 NEAR EU3

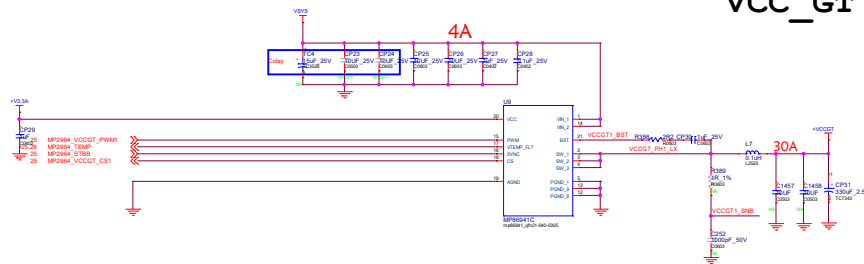


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Size B	Document Number	25_PWR_IMVP CONTROLLER			Rev 1.0
Date: Monday, March 14, 2022 <Doc>	Sheet 25			of 45	

VCC_CORE



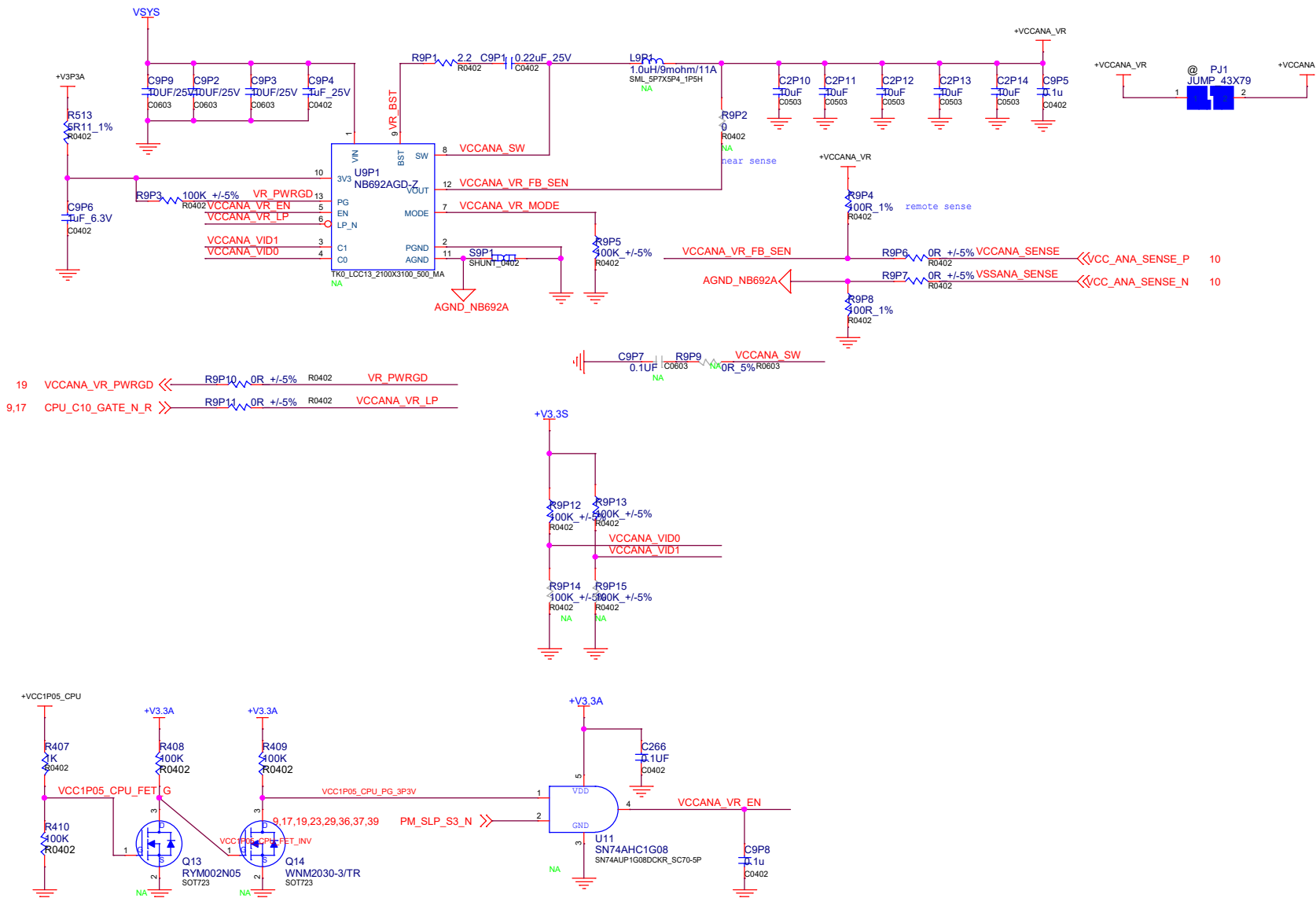
VCC_GT



Colay

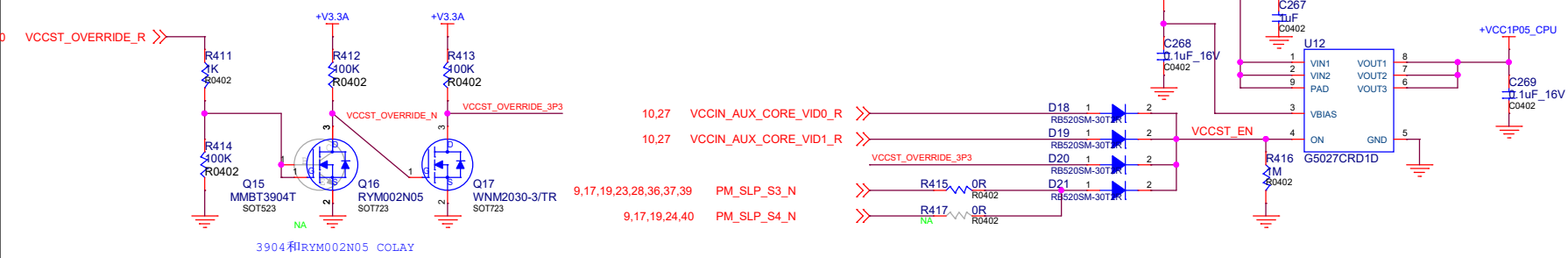


28 VCCANA POWER

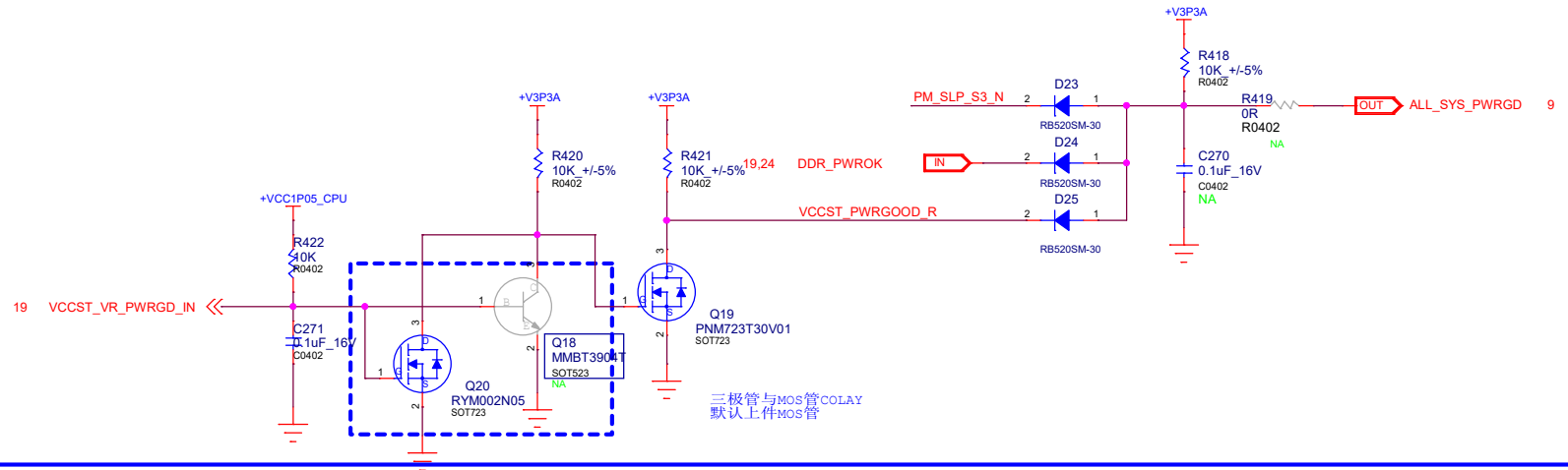


VCCANA	
VOUT	1.05V
SWITCHING FREQUENCY	750 KHZ
ICC MAX	3.6A
VR/MOSFET MPN	NB692D
INDUCTOR MPN	TMP00315H-1R0MG
INDUCTOR IRMS	3.6A
INDUCTOR ISAT	5.8 A
INDUCTOR DCR(TYP)	41 MILLI OHM

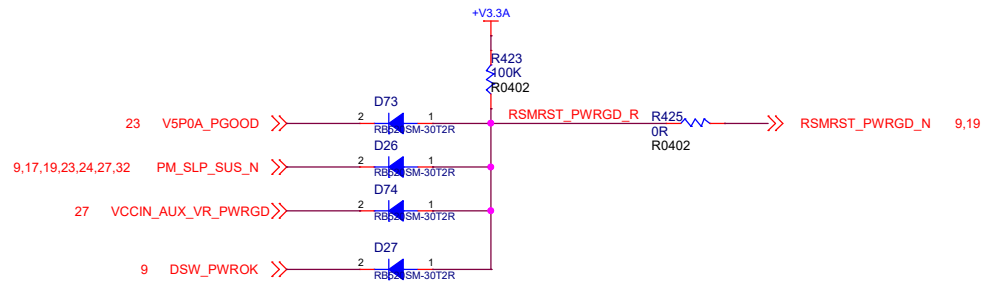
+VCC1P05_CPU

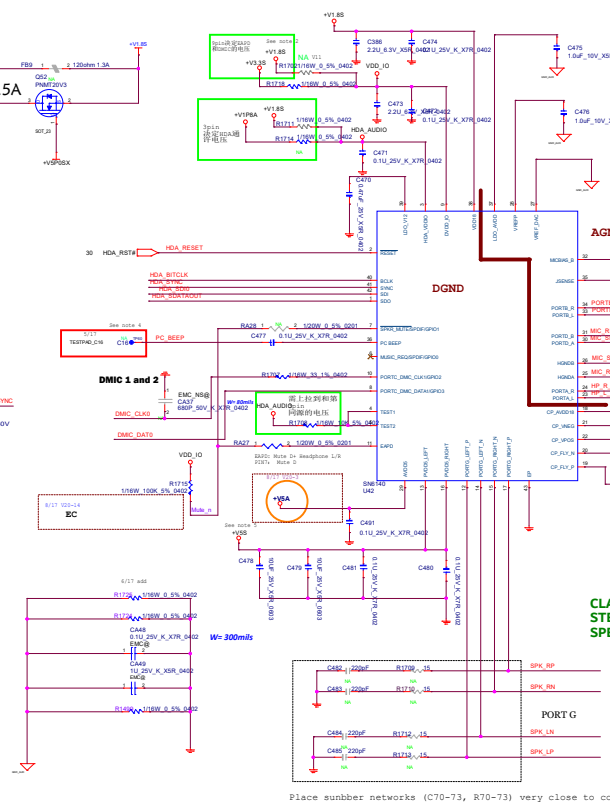
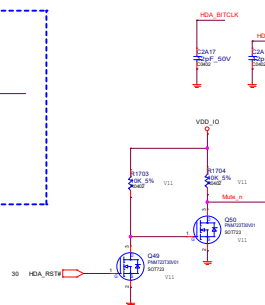
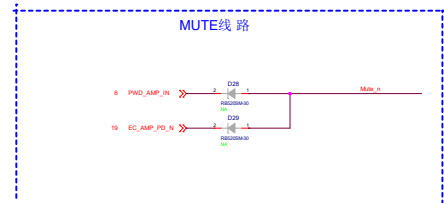
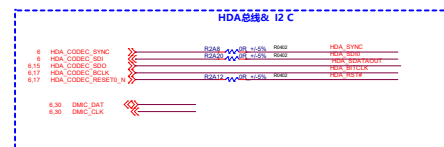


VCCST_VR_PWRGD_IN



RSMRST PWRGD

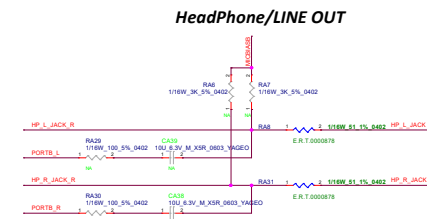




Notes:

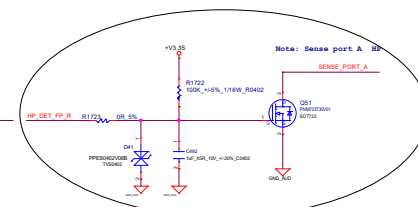
- 1.VDD_HDA must be connected to same HDA bus power supply that is used for PCB bus controller(3.3V or 1.8V or 1.5V).
- 2.VDD_IO sets the DMIC, SPDIF, EAPD and GPIO levels (3.3V or 1.8V).
- 3.Make sure that HDA BITCLK, SYNC, SDATA_OUT and RESSETN have series terminators at the controller.
- 4.PC BEEP input level is 1.8V max, need to attenuate signal if 3.3V level.

Detect/switch headset jack: The CX11880 has integrated hum noise attenuation for external powered speakers with high power supply leakage connected to jack when the system is off. Some speakers have excessive leakage and the internal solution may not attenuate the noise sufficiently. Optional solution is connect AVDD5V(pin 29) to an always on supply. Requires 15uA while system is off/2mA max.in runtime.

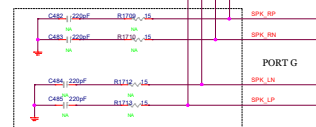


EXT. MIC/LINE IN

Apple -> EXT_MIC_A, HGND8
Nokia -> EXT_MIC_B, HGND8

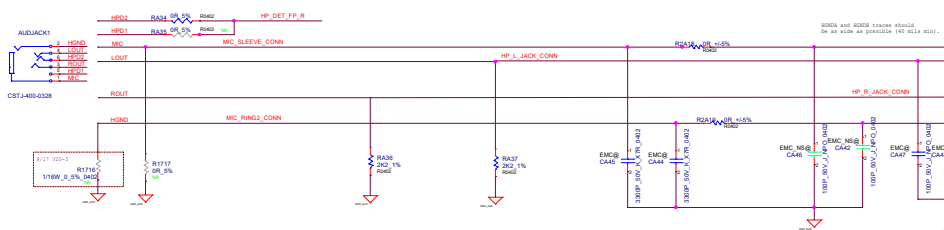


CLASS-D TO STEREO SPEAKERS

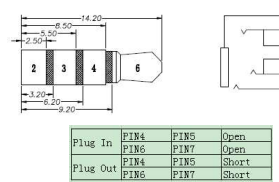
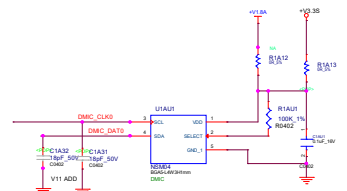


Place snubber networks (C70-73, R70-73) very close to codec pins.

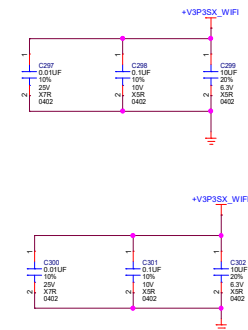
Audio CONN



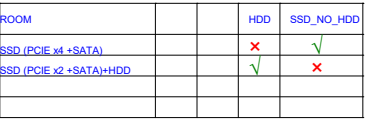
NEAR AUDIO CONN



32 WLAN module



SATA/PCIE SSD:1X



EMMC

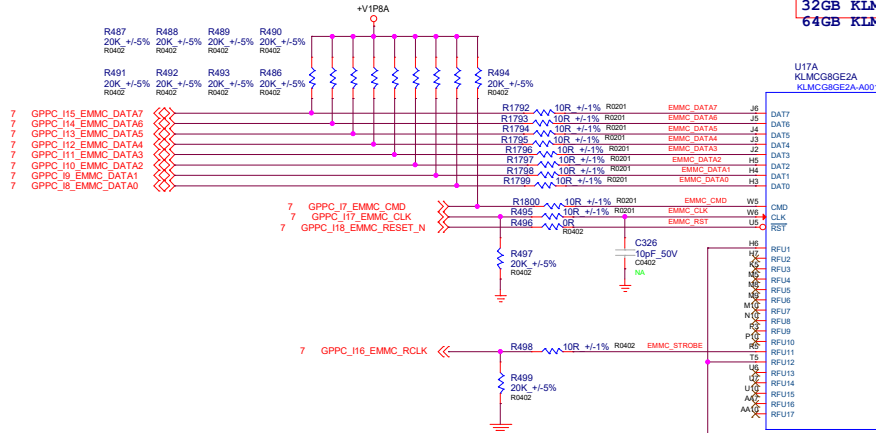
emMC AVL:

Samsung

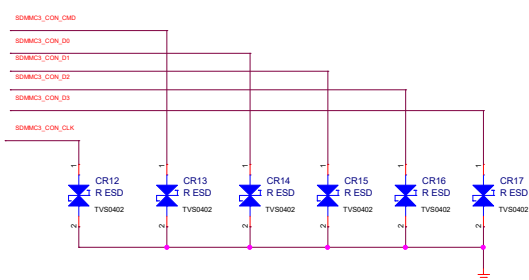
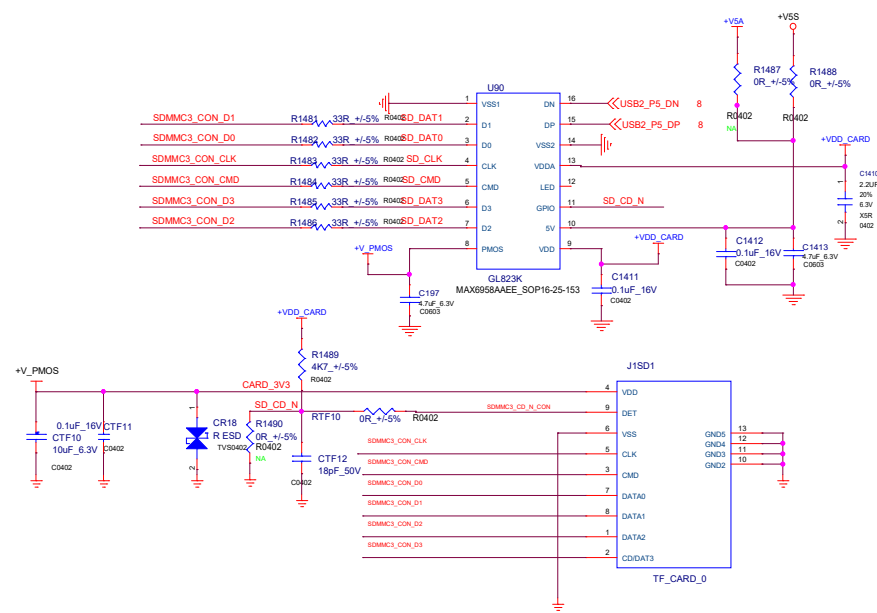
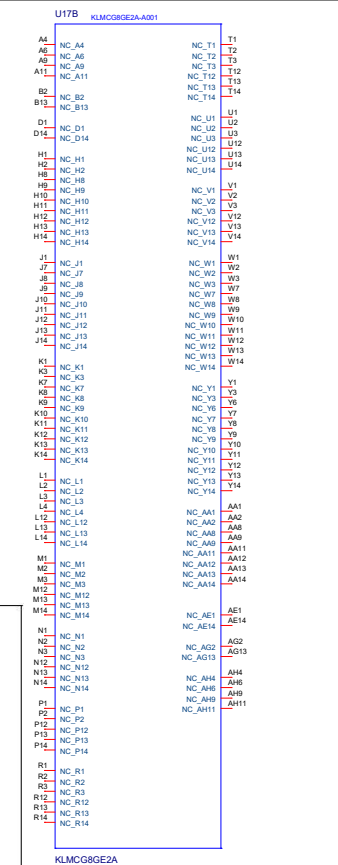
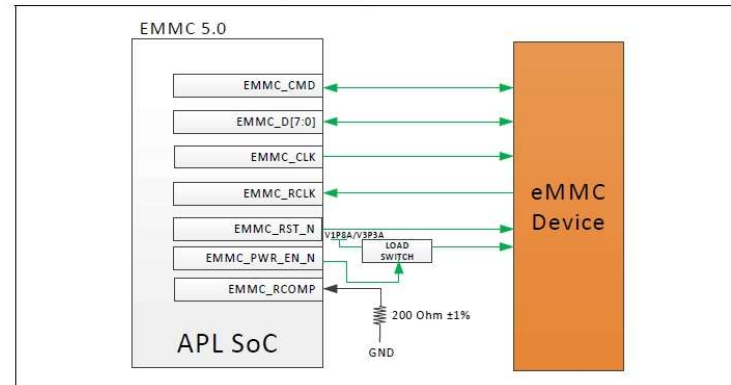
16GB KLMAG2WEMB-B031 / KLMAG2GEAC-B031

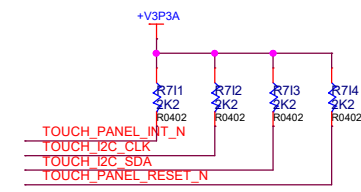
32GB KLMBG4WECB-B031 / KLMBG4GEAC-B031

64GB KLTCG8WECB-B031 / KLTCG8GEAC-B031

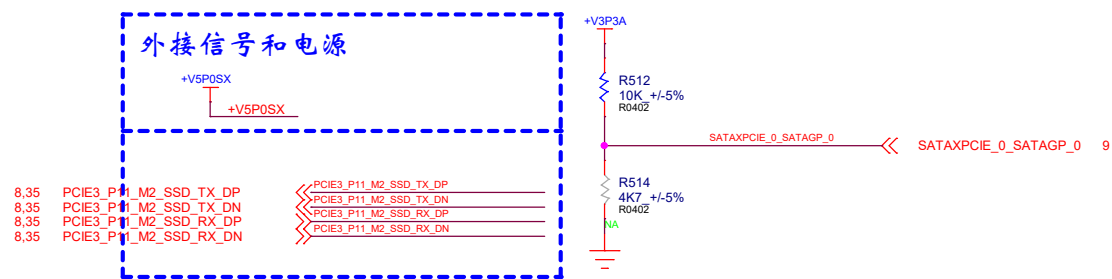
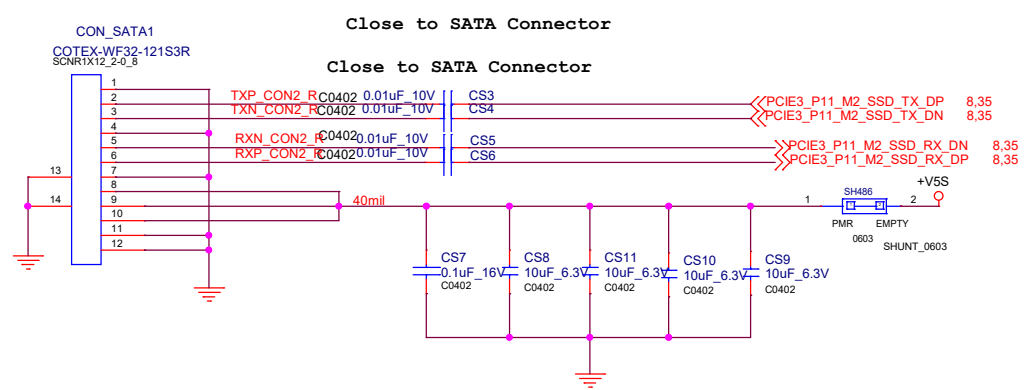


embedded MultiMedia Card (eMMC*) Interface



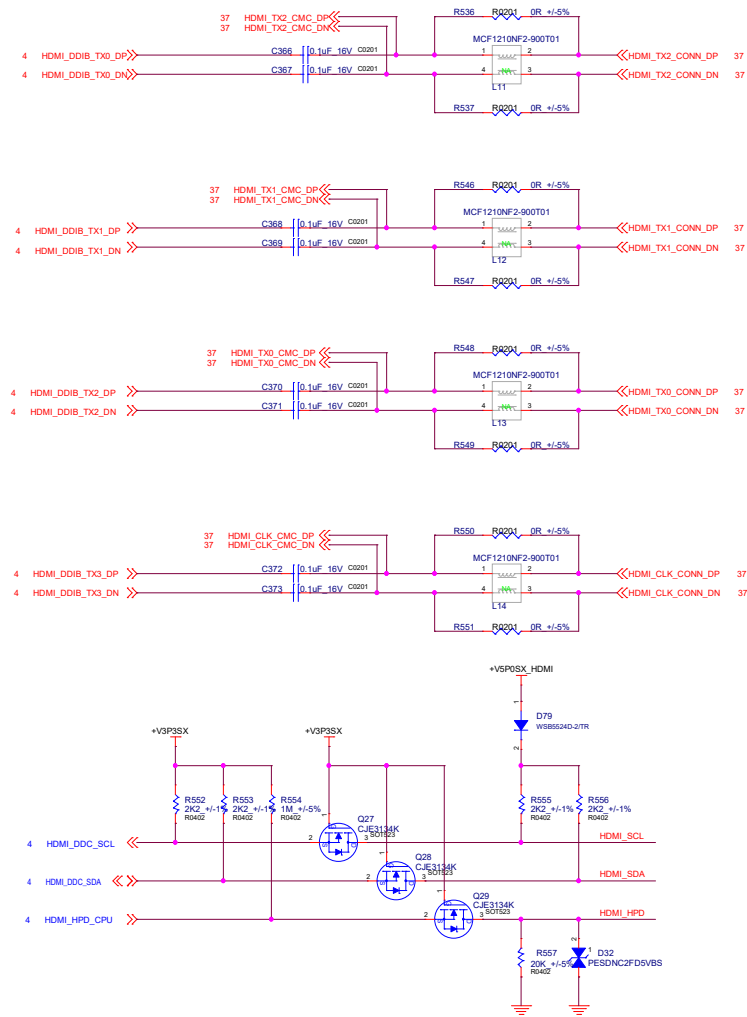


硬盘连接器/CON_HDD

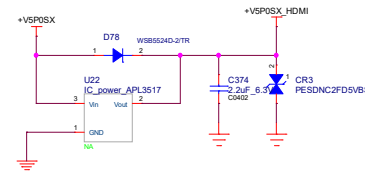
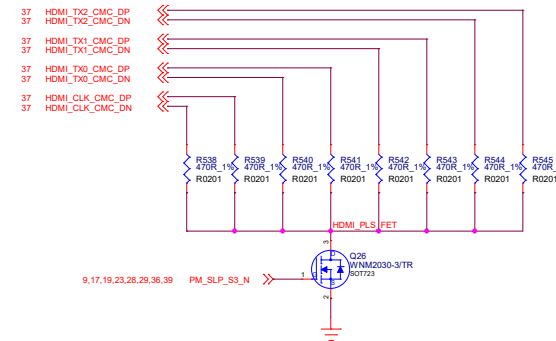


外接信号和电源

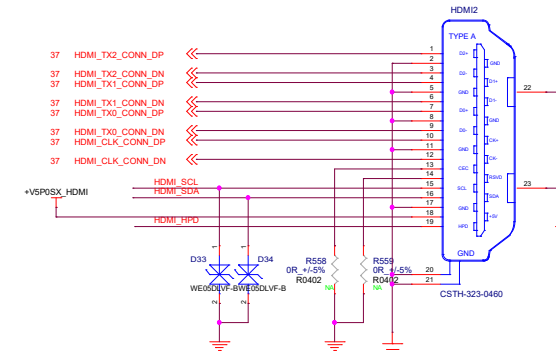




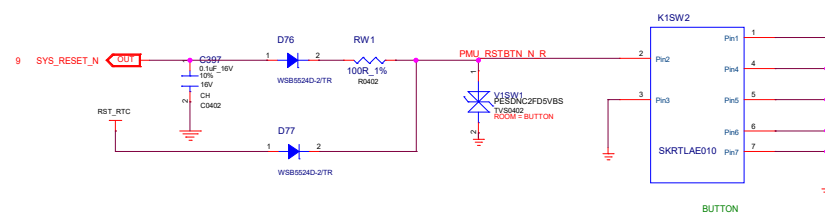
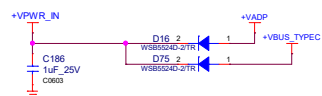
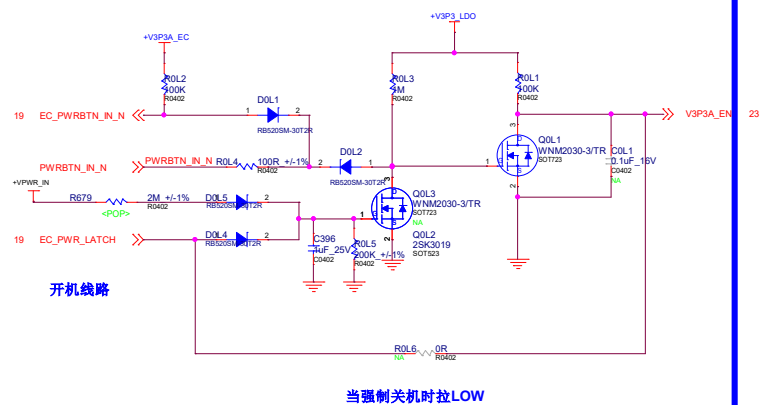
HDMI LEVEL SHIFTERS 1.65Gbps



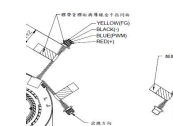
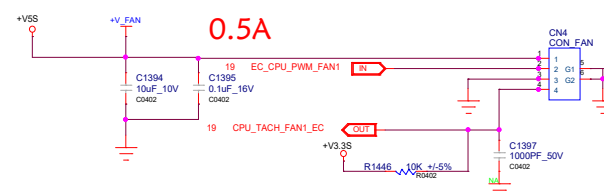
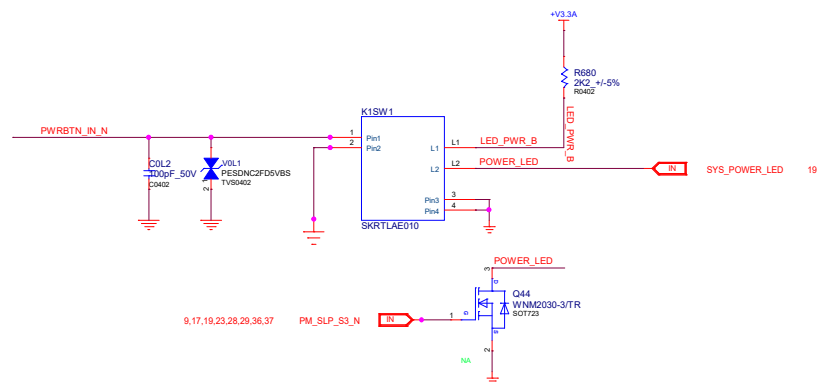
HDMI CONNECTOR

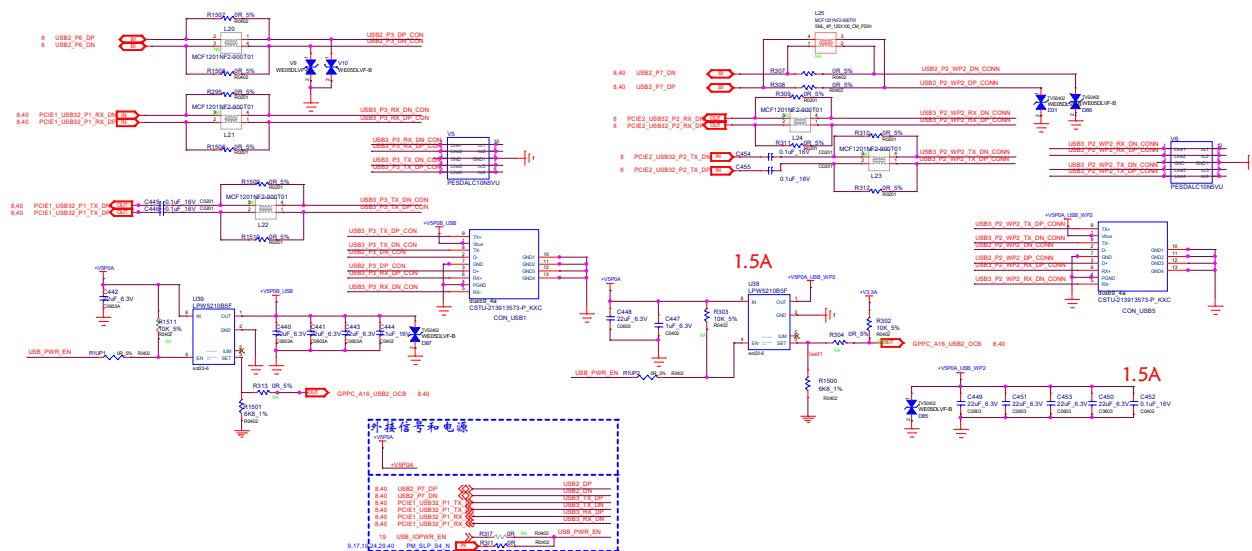


39 CON KB&PWR SW&LED

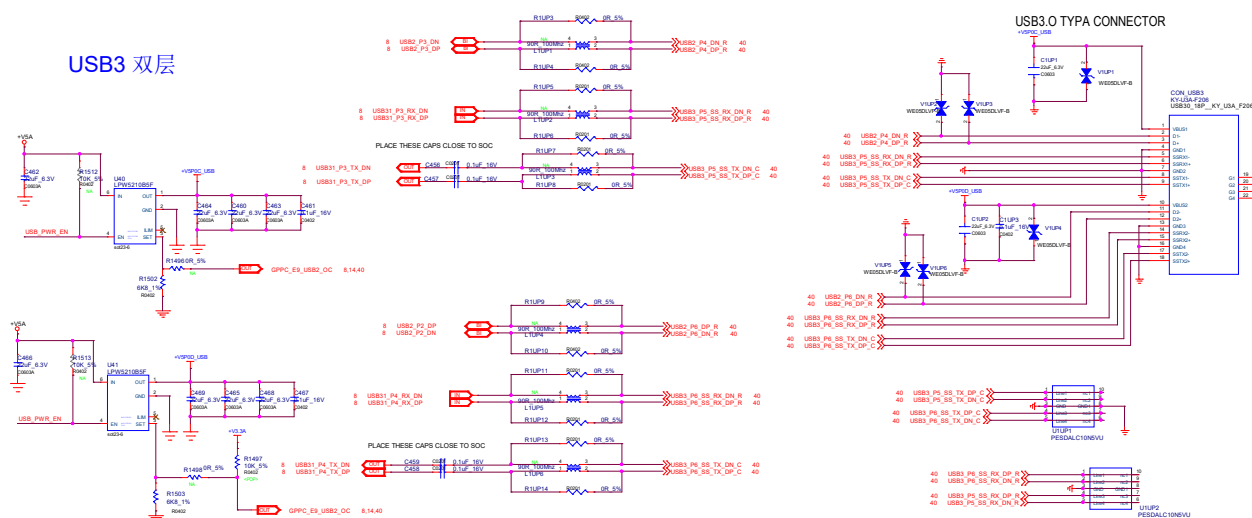


LED控制

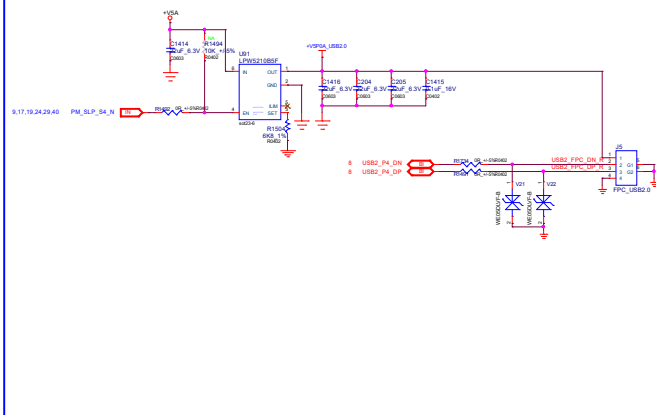




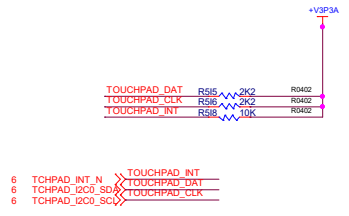
USB3 双层



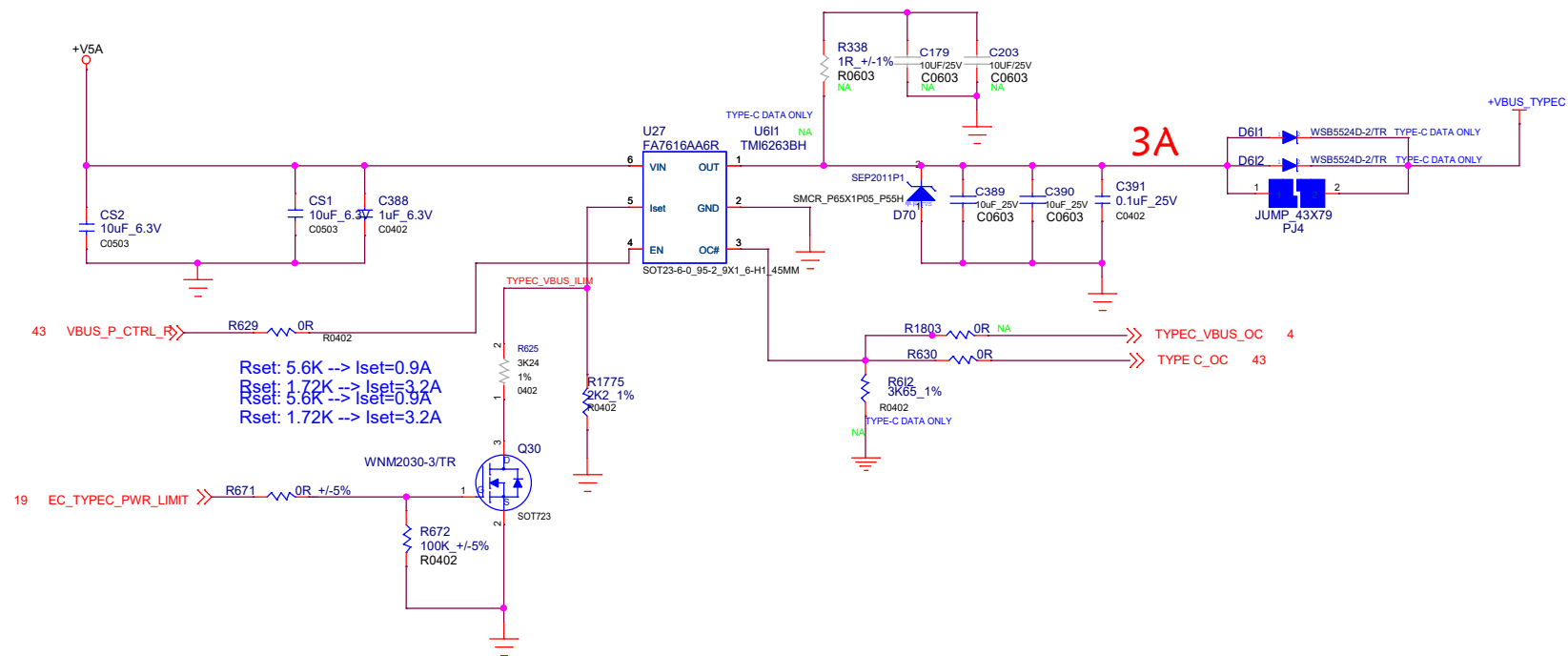
预留USB2.0 (FPC)

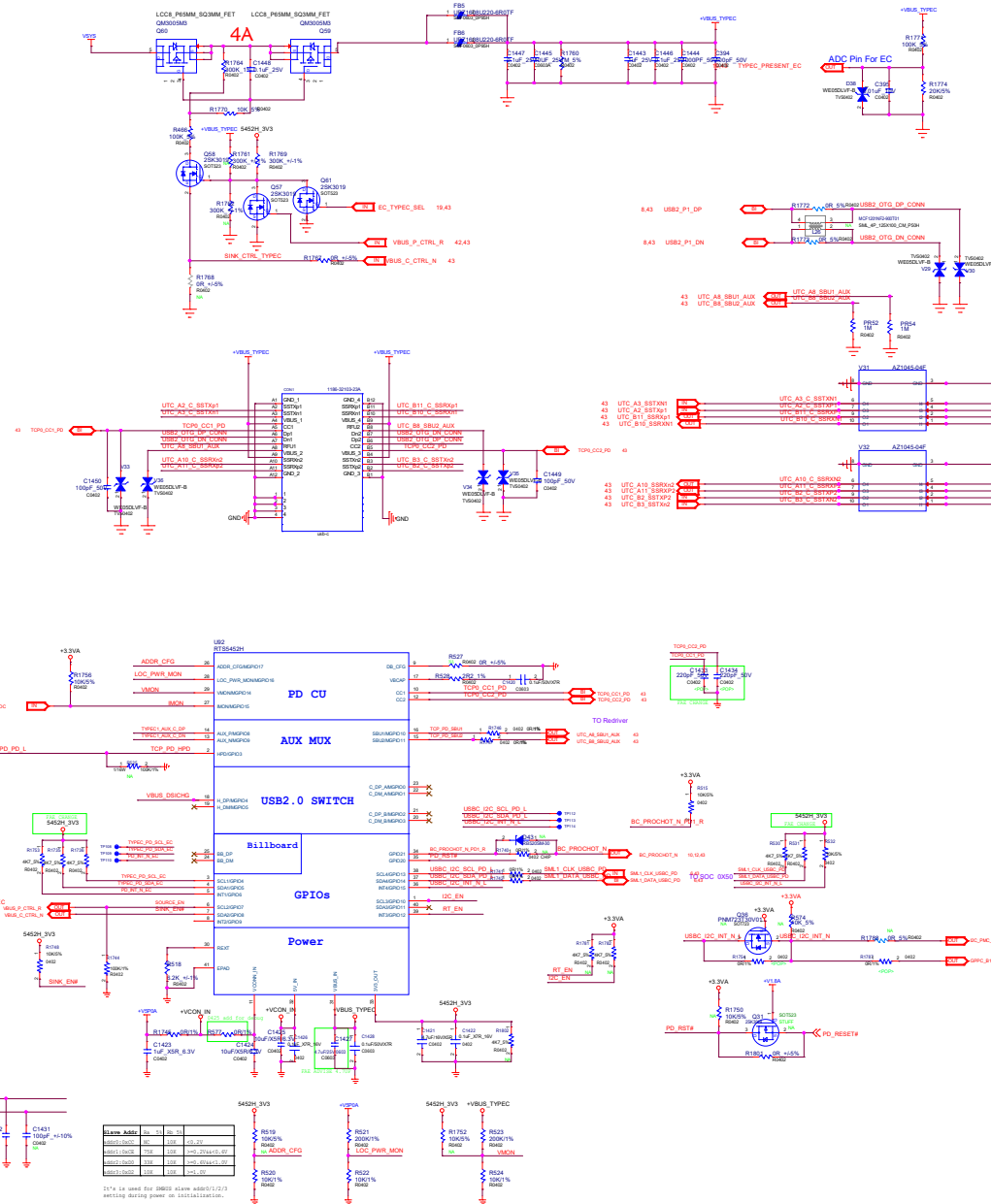


LID/霍尔传感器



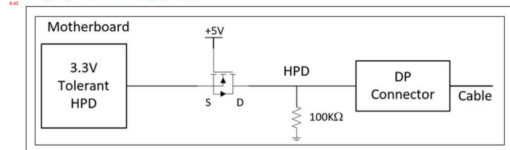
42 USB-C Power





Type C	TCPx_TX_N0	DDIx_DP_LANE0_N
	TCPx_TX_P0	DDIx_DP_LANE0_P
	TCPx_TX_N1	DDIx_DP_LANE2_N
	TCPx_TX_P1	DDIx_DP_LANE2_P
	TCPx_TXRX_N0	DDIx_DP_LANE1_N
	TCPx_TXRX_P0	DDIx_DP_LANE1_P
	TCPx_TXRX_N1	DDIx_DP_LANE3_N
	TCPx_TXRX_P1	DDIx_DP_LANE3_P
	TCPx_AUX_P	DDIx_DP_AUX_P
	TCPx_AUX_N	DDIx_DP_AUX_N
	DDSP_HPDx	DPx_HPD

DisplayPort Hot Plug Detect



V11 Changne list

Page 43: change to +3.3VA from +3.3VS, change to +V3P3SX from +3.3VS(EQ check issue)

Page 23: Q12 NA

Page 42: U6I2 NA
Page 43: B1B1 NA

Page 23: R1P4 NA to ment NB690 operates in normal mode

Page 38: R705,R706 NA

Page 26: delete U2, U93,U94 colay,change U7,U8,U9 footprint to mp86941_qfn21-040-0305 from MP86941_QFN21_0D4_3X5_H0D8C

Page 25: mark R379 15W=1.87K, 6W/7W=2K from MPS advice

Page 26: reserve C1453~C1458

Page 39: reserve R0L6 to Q0L1 for EC to control 3P3A

Page 19: R242 net to BATT_ID_EC, EC PIN94 net to EC_SIN1

Page 44: R299 Change to 22K

Page 06: R13,R14 NA

Page 43: Q36,R1788,R574 NA, R1754,R1787 mount, R532 NA

Page 26: DEL +VCCANA_VR due to BIOS can enable FIVR to replace MBVR
(U9P1,L9P1,U11,Q13,Q14 NA)

Page 18: U0F1 change to 16M(W25Q128JVSIQ) from 32M

Page 21:Change C176 to 0.47uF from 0.1uF to delay VSYS to 3ms

Page 36:Change Q47 PIN3 netname to HDMIA_HPD_C form HDMIA_HPD

Page 19:Change EC PIN85 PM_RSMRST_N to PIN67, PIN85 renet: HDMIA_CEC ,
DEL: R244,R246,RT_CHG1,RT_CPU1

Page 36: ADD CEC Circuit

Page 37: ADD CEC Circuit

Page 26: Change R384,R386,R388 to 2.2R from 0R to reduce SW voltage

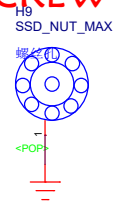
Page 32: R1F23 NA duplication

Page 33: R478 NA duplication

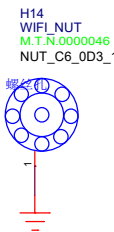
Page 30: R1711 MOUNT,R1714 NA to ment vender request

Page 25: R342,R341 MOUNT for EC burn MPS FW

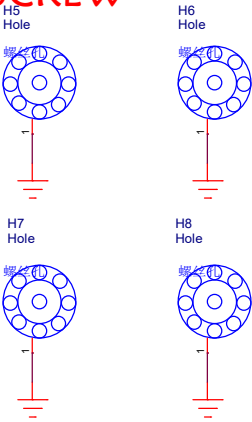
SSD
SCREW



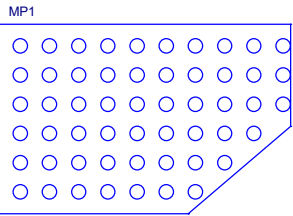
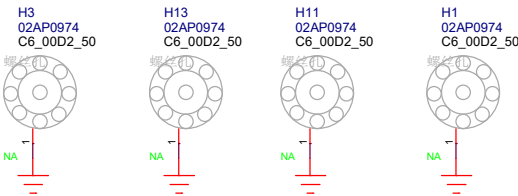
WIFI
NUT



CPU
SCREW



ME Hole



PingBiZhao

